

Virtex-4Q FPGA Electrical Characteristics

Defense-grade Virtex[®]-4Q FPGAs are available in -10 speed grade and are qualified for industrial ($T_j = -40^{\circ}\text{C}$ to $+100^{\circ}\text{C}$), and military ($T_j = -55^{\circ}\text{C}$ to $+125^{\circ}\text{C}$) operational temperatures. Some devices are also available using a -11 speed specification for industrial temperature only.

Defense-grade Virtex-4Q FPGA DC and AC characteristics are specified for military and industrial grades only. Except the operating temperature range or unless otherwise noted, all the DC and AC electrical parameters are the same for a particular speed grade (that is, the timing characteristics of a -10 speed grade military device are the same as for a -10 speed grade industrial device).

All supply voltage and junction temperature specifications are representative of worst-case conditions. The parameters included are common to popular designs and typical applications.

This Defense-grade Virtex-4Q FPGA data sheet is part of an overall set of documentation on the Virtex-4 family of FPGAs available on the Xilinx website:

- [DS112](#), *Virtex-4 Family Overview*
- [UG070](#), *Virtex-4 User Guide*
- [UG071](#), *Virtex-4 FPGA Configuration Guide*
- [UG073](#), *XtremeDSP for Virtex-4 FPGAs User Guide*
- [UG075](#), *Virtex-4 Packaging and Pinout Specifications*
- [UG072](#), *Virtex-4 FPGA PCB Designer's Guide*

All specifications are subject to change without notice.

Virtex-4Q FPGA DC Characteristics

Table 1: Absolute Maximum Ratings⁽¹⁾

Symbol	Description	Values	Units
V_{CCINT}	Internal supply voltage relative to GND	-0.5 to 1.32	V
V_{CCAUX}	Auxiliary supply voltage relative to GND	-0.5 to 3.0	V
V_{CCO}	Output drivers supply voltage relative to GND	-0.5 to 3.75	V
V_{BATT}	Key memory battery backup supply	-0.5 to 4.05	V
V_{REF}	Input reference voltage	-0.3 to 3.75	V
V_{IN}	I/O input voltage relative to GND (all user and dedicated I/Os)	-0.75 to 4.05	V
	I/O input voltage relative to GND ⁽³⁾ (restricted to maximum of 100 user I/Os) ⁽⁴⁾	-0.85 to 4.3	V
	2.5V or below I/O input voltage relative to GND (user and dedicated I/Os)	-0.75 to $V_{CCO} + 0.5$	V
V_{TS}	Voltage applied to 3-state 3.3V output ⁽³⁾ (all user and dedicated I/Os)	-0.75 to 4.05	V
	Voltage applied to 3-state 3.3V output ⁽³⁾ (restricted to maximum of 100 user I/Os) ⁽⁴⁾	-0.85 to 4.3	V
	2.5V or below I/O input voltage relative to GND (user and dedicated I/Os)	-0.75 to $V_{CCO} + 0.5$	V
V_{TRX}	Terminal receive supply voltage relative to GND	-0.5 to 3.0	V
V_{TTX}	Terminal transmit supply voltage relative to GND	-0.5 to 1.65	V
T_{STG}	Storage temperature (ambient)	-65 to 150	$^{\circ}\text{C}$
T_{SOL}	Maximum soldering temperature ⁽²⁾	+220	$^{\circ}\text{C}$

Table 1: Absolute Maximum Ratings⁽¹⁾ (Cont'd)

Symbol	Description	Values	Units
T_j	Maximum junction temperature ⁽²⁾	+125	°C

Notes:

- Stresses beyond those listed under Absolute Maximum Ratings might cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those listed under Operating Conditions is not implied. Exposure to Absolute Maximum Ratings conditions for extended periods of time might affect device reliability.
- For soldering guidelines and thermal considerations, see the *Virtex-4 Packaging and Pinout Specifications*.
- For 3.3V I/O operation, refer to the *Virtex-4 User Guide*, Chapter 6, 3.3V I/O Design Guidelines.
- For more flexibility in specific designs, a maximum of 100 user I/O s can be stressed beyond the normal spec for no more than 20% of a data period. There are no bank restrictions.

Table 2: Recommended Operating Conditions

Symbol	Description	Min	Max	Units
V_{CCINT}	Internal supply voltage relative to GND	1.14	1.26	V
V_{CCAUX}	Auxiliary supply voltage relative to GND	2.375	2.625	V
V_{CCO} ⁽¹⁾⁽³⁾⁽⁴⁾⁽⁵⁾	Supply voltage relative to GND	1.14	3.45	V
V_{IN}	3.3V supply voltage relative to GND	GND – 0.20	3.45	V
	2.5V and below supply voltage relative to GND	GND – 0.20	$V_{CCO} + 0.2$	V
V_{BATT} ⁽²⁾	Battery voltage relative to GND	1.0	3.6	V

Notes:

- Configuration data is retained even if V_{CCO} drops to 0V.
- V_{BATT} is required only when using bitstream encryption. If battery is not used, connect V_{BATT} to either ground or V_{CCAUX} .
- For 3.3V I/O operation, refer to the *Virtex-4 User Guide*.
- Includes V_{CCO} of 1.2V, 1.5V, 1.8V, 2.5V, and 3.3V.
- The configuration output supply voltage V_{CC_CONFIG} is also known as V_{CCO_0} .

Table 3: DC Characteristics Over Recommended Operating Conditions

Symbol	Description	Min	Typ	Max	Units
V_{DRINT}	Data retention V_{CCINT} voltage (below which configuration data might be lost)	0.9	–	–	V
V_{DRI}	Data retention V_{CCAUX} voltage (below which configuration data might be lost)	2.0	–	–	V
I_{REF}	V_{REF} current per pin	–	–	10	μA
I_L	Input or output leakage current per pin (sample-tested)	–	–	10	μA
C_{IN}	Input capacitance (sample-tested)	–	–	10	pF
I_{RPU} ⁽¹⁾	Pad pull-up (when selected) @ $V_{IN} = 0V$, $V_{CCO} = 3.3V$	5	–	200	μA
	Pad pull-up (when selected) @ $V_{IN} = 0V$, $V_{CCO} = 3.0V$	5	–	125	μA
	Pad pull-up (when selected) @ $V_{IN} = 0V$, $V_{CCO} = 2.5V$	5	–	120	μA
	Pad pull-up (when selected) @ $V_{IN} = 0V$, $V_{CCO} = 1.8V$	5	–	60	μA
	Pad pull-up (when selected) @ $V_{IN} = 0V$, $V_{CCO} = 1.5V$	5	–	40	μA
I_{RPD} ⁽¹⁾	Pad pull-down (when selected) @ $V_{IN} = V_{CCO}$	5	–	100	μA
I_{BATT} ⁽¹⁾	Battery supply current	–	75	–v	nA
n	Temperature diode ideality factor	–	1.02	–	n
r	Series resistance	–	2	–	Ω

Notes:

- Typical values are specified at nominal voltage, 25°C.

Table 4: Quiescent Supply Current

Symbol	Description	Device	Typ ⁽¹⁾		Max	Units
			I-Grade	M-Grade		
I _{CCINTQ}	Quiescent V _{CCINT} supply current	XQ4VLX25	–	139	Note 4	mA
		XQ4VLX40	121	218	Note 4	mA
		XQ4VLX60	167	301	Note 4	mA
		XQ4VLX80	220	–	Note 4	mA
		XQ4VLX100	292	–	Note 4	mA
		XQ4VLX160	384	–	Note 4	mA
		XQ4VSX55	271	488	Note 4	mA
		XQ4VFX60	203	365	Note 4	mA
		XQ4VFX100	311	–	Note 4	mA
I _{CCOQ}	Quiescent V _{CCO} supply current	XQ4VLX25	–	2.50	Note 4	mA
		XQ4VLX40	1.25	2.50	Note 4	mA
		XQ4VLX60	1.5	3.00	Note 4	mA
		XQ4VLX80	1.5	–	Note 4	mA
		XQ4VLX100	1.75	–	Note 4	mA
		XQ4VLX160	2.5	–	Note 4	mA
		XQ4VSX55	1.5	3.00	Note 4	mA
		XQ4VFX60	1.5	3.00	Note 4	mA
		XQ4VFX100	1.75	–	Note 4	mA
I _{CCAUXQ}	Quiescent V _{CCAUX} supply current	XQ4VLX25	–	54	Note 4	mA
		XQ4VLX40	43	65	Note 4	mA
		XQ4VLX60	74	111	Note 4	mA
		XQ4VLX80	83	–	Note 4	mA
		XQ4VLX100	95	–	Note 4	mA
		XQ4VLX160	133	–	Note 4	mA
		XQ4VSX55	91	137	Note 4	mA
		XQ4VFX60	80	120	Note 4	mA
		XQ4VFX100	98	–	Note 4	mA

Notes:

1. Typical values are specified at nominal voltage, 25°C.
2. Typical values are for blank configured devices with no output current loads, no active input pull-up resistors, all I/O pins are 3-state and floating.
3. If DCI or differential signaling is used, more accurate quiescent current estimates can be obtained by using the [Power Estimator](#) or XPOWER tool.
4. Use the XPower Estimator (XPE) tool to calculate maximum static power for specific process, voltage, and temperature conditions.

Power-On Power Supply Requirements

Xilinx FPGAs require a certain amount of supply current during power-on to insure proper device initialization. The actual current consumed depends on the power-on ramp rate of the power supply.

The power supplies can be turned on in any sequence, though the specifications shown in [Table 5](#) are for the recommended power-on sequence of V_{CCINT} , V_{CCAUX} , V_{CCO} . Xilinx does not specify the current for other power-on sequences.

[Table 5](#) shows the maximum current required by Virtex-4Q devices for proper power-on and configuration.

Once initialized and configured, use the XPOWER tool to estimate current drain on these supplies.

Table 5: Maximum Power-On Current for Virtex-4Q Devices

Device	I_{CCINT}		I_{CCAUX}		I_{CCO}		Units
	Typ ⁽¹⁾	Max ⁽²⁾	Typ ⁽¹⁾	Max ⁽²⁾	Typ ⁽¹⁾	Max ⁽²⁾	
XQ4VLX25	220	2862	85	555	75	390	mA
XQ4VLX40	315	3150	110	705	75	390	mA
XQ4VLX60	300	3960	225	825	150	390	mA
XQ4VLX80	400	2550	280	350	150	275	mA
XQ4VLX100 ⁽³⁾	585	6912	335	1050	200	450	mA
XQ4VLX160 ⁽³⁾	855	8325	500	1238	250	600	mA
XQ4VSX55	520	5355	225	930	150	450	mA
XQ4VFX60	410	4680	220	1050	150	435	mA
XQ4VFX100	511	3300	278	500	200	300	mA

Notes:

1. Typical values are specified at nominal voltage, 25°C.
2. Maximum values are specified under worst-case process, voltage, and military temperature conditions.
3. XQ4VLX100 and XQ4VLX160 are offered in I grade only. Values represent worst-case process, voltage and industrial temperature operating conditions.

Table 6: Power Supply Ramp Time

Symbol	Description	Ramp Time	Units
V_{CCINT}	Internal supply voltage relative to GND	0.20 to 50.0	ms
V_{CCO}	Output drivers supply voltage relative to GND	0.20 to 50.0	ms
V_{CCAUX}	Auxiliary supply voltage relative to GND	0.20 to 50.0	ms

SelectIO™ DC Input and Output Levels

Values for V_{IL} and V_{IH} are recommended input voltages. Values for I_{OL} and I_{OH} are guaranteed over the recommended operating conditions at the V_{OL} and V_{OH} test points. Only selected standards are tested. These are chosen to ensure that all standards meet their specifications. The selected standards are tested at a minimum V_{CCO} with the respective V_{OL} and V_{OH} voltage levels shown. Other standards are sample tested.

Table 7: Select I/O DC Input and Output Levels

IOSTANDARD Attribute	V_{IL}		V_{IH}		V_{OL}	V_{OH}	I_{OL}	I_{OH}
	V, Min	V, Max	V, Min	V, Max	V, Max	V, Min	mA	mA
LVTTTL	-0.2	0.8	2.0	3.45	0.4	2.4	Note 3	Note 3
LVC MOS33	-0.2	0.8	2.0	3.45	0.4	$V_{CCO} - 0.4$	Note 3	Note 3 Note 6
LVC MOS25	-0.3	0.7	1.7	$V_{CCO} + 0.3$	0.4	$V_{CCO} - 0.4$	Note 3	Note 3
LVC MOS18	-0.3	35% V_{CCO}	65% V_{CCO}	$V_{CCO} + 0.3$	0.4	$V_{CCO} - 0.45$	Note 4	Note 4
LVC MOS15	-0.3	35% V_{CCO}	65% V_{CCO}	$V_{CCO} + 0.3$	0.4	$V_{CCO} - 0.45$	Note 4	Note 4 Note 6
PCI33_3 ⁽⁵⁾	-0.2	30% V_{CCO}	50% V_{CCO}	V_{CCO}	10% V_{CCO}	90% V_{CCO}	1.5	-0.5
PCI66_3 ⁽⁵⁾	-0.2	30% V_{CCO}	50% V_{CCO}	V_{CCO}	10% V_{CCO}	90% V_{CCO}	1.5	-0.5
PCI-X ⁽⁵⁾	-0.2	35% V_{CCO}	50% V_{CCO}	V_{CCO}	10% V_{CCO}	90% V_{CCO}	1.5	-0.5
GTLP	-0.3	$V_{REF} - 0.1$	$V_{REF} + 0.1$	-	0.6	N/A	36	N/A
GTL	-0.3	$V_{REF} - 0.05$	$V_{REF} + 0.05$	-	0.4	N/A	32	N/A
HSTL I ⁽²⁾	-0.3	$V_{REF} - 0.1$	$V_{REF} + 0.1$	$V_{CCO} + 0.3$	0.4	$V_{CCO} - 0.4$	8	-8
HSTL II ⁽²⁾	-0.3	$V_{REF} - 0.1$	$V_{REF} + 0.1$	$V_{CCO} + 0.3$	0.4	$V_{CCO} - 0.4$	16	-16
HSTL III ⁽²⁾	-0.3	$V_{REF} - 0.1$	$V_{REF} + 0.1$	$V_{CCO} + 0.3$	0.4	$V_{CCO} - 0.4$	24	-8
HSTL IV ⁽²⁾	-0.3	$V_{REF} - 0.1$	$V_{REF} + 0.1$	$V_{CCO} + 0.3$	0.4	$V_{CCO} - 0.4$	48	-8
DIFF HSTL II ⁽²⁾	-0.3	50% $V_{CCO} - 0.1$	50% $V_{CCO} + 0.1$	$V_{CCO} + 0.3$	0.4	$V_{CCO} - 0.4$	-	-
SSTL2 I	-0.3	$V_{REF} - 0.15$	$V_{REF} + 0.15$	$V_{CCO} + 0.3$	$V_{TT} - 0.61$	$V_{TT} + 0.61$	8.1	-8.1
SSTL2 II	-0.3	$V_{REF} - 0.15$	$V_{REF} + 0.15$	$V_{CCO} + 0.3$	$V_{TT} - 0.81$	$V_{TT} + 0.81$	16.2	-16.2
DIFF SSTL2 II	-0.3	50% $V_{CCO} - 0.15$	50% $V_{CCO} + 0.15$	$V_{CCO} + 0.3$	0.5	$V_{CCO} - 0.5$	-	-
SSTL18 I	-0.3	$V_{REF} - 0.125$	$V_{REF} + 0.125$	$V_{CCO} + 0.3$	$V_{TT} - 0.47$	$V_{TT} + 0.47$	6.7	-6.7
SSTL18 II	-0.3	$V_{REF} - 0.125$	$V_{REF} + 0.125$	$V_{CCO} + 0.3$	$V_{TT} - 0.60$	$V_{TT} + 0.60$	13.4	-13.4
DIFF SSTL18 II	-0.3	50% $V_{CCO} - 0.125$	50% $V_{CCO} + 0.125$	$V_{CCO} + 0.3$	0.4	$V_{CCO} - 0.4$	-	-

Notes:

1. Tested according to relevant specifications.
2. Applies to both 1.5V and 1.8V HSTL.
3. Using drive strengths of 2, 4, 6, 8, 12, 16, or 24 mA.
4. Using drive strengths of 2, 4, 6, 8, 12, or 16 mA.
5. For more information on PCI33_3, PCI66_3, and PCI-X refer to the *Virtex-4 FPGA User Guide, SelectIO Resources*, Chapter 6.
6. LVC MOS15 4 mA, LVC MOS33 6 mA, LVC MOS33 8 mA have reduced drive strength (I_{OH}) by 20%.

LDT DC Specifications (LDT_25)

Table 8: LDT DC Specifications

Symbol	DC Parameter	Conditions	Min	Typ	Max	Units
V_{CCO}	Supply Voltage		2.38	2.5	2.63	V
V_{OD}	Differential Output Voltage ⁽¹⁾⁽²⁾	$R_T = 100\Omega$ across Q and \bar{Q} signals	495	600	750	mV
ΔV_{OD}	Change in V_{OD} Magnitude		-15		15	mV
V_{OCM}	Output Common Mode Voltage	$R_T = 100\Omega$ across Q and \bar{Q} signals	495	600	715	mV
ΔV_{OCM}	Change in V_{OCM} Magnitude		-15		15	mV
V_{ID}	Input Differential Voltage		200	600	1000	mV
ΔV_{ID}	Change in V_{ID} Magnitude		-15		15	mV
V_{ICM}	Input Common Mode Voltage		440	600	780	mV
ΔV_{ICM}	Change in V_{ICM} Magnitude		-15		15	mV

Notes:

1. Recommended input maximum voltage not to exceed $V_{CCO} + 0.2V$.
2. Recommended input minimum voltage not to go below $-0.5V$.

LVDS DC Specifications (LVDS_25)

Table 9: LVDS DC Specifications

Symbol	DC Parameter	Conditions	Min	Typ	Max	Units
V_{CCO}	Supply Voltage		2.38	2.5	2.63	V
V_{OH}	Output High Voltage for Q and \bar{Q}	$R_T = 100\Omega$ across Q and \bar{Q} signals			1.602	V
V_{OL}	Output Low Voltage for Q and \bar{Q}	$R_T = 100\Omega$ across Q and \bar{Q} signals	0.898			V
V_{ODIFF}	Differential Output Voltage ⁽¹⁾⁽²⁾ (Q - \bar{Q}), Q = High ($\bar{Q} - Q$), \bar{Q} = High	$R_T = 100\Omega$ across Q and \bar{Q} signals	247	350	550	mV
V_{OCM}	Output Common-Mode Voltage	$R_T = 100\Omega$ across Q and \bar{Q} signals	1.100	1.250	1.375	V
V_{IDIFF}	Differential Input Voltage (Q - \bar{Q}), Q = High ($\bar{Q} - Q$), \bar{Q} = High		100	350	600	mV
V_{ICM}	Input Common-Mode Voltage		0.3	1.2	2.2	V

Notes:

1. Recommended input maximum voltage not to exceed $V_{CCO} + 0.2V$.
2. Recommended input minimum voltage not to go below $-0.5V$.

Extended LVDS DC Specifications (LVDSEXT_25)

Table 10: Extended LVDS DC Specifications

Symbol	DC Parameter	Conditions	Min	Typ	Max	Units
V_{CCO}	Supply Voltage		2.38	2.5	2.63	V
V_{OH}	Output High Voltage for Q and \bar{Q}	$R_T = 100\Omega$ across Q and \bar{Q} signals	–	–	1.785	V
V_{OL}	Output Low Voltage for Q and \bar{Q}	$R_T = 100\Omega$ across Q and \bar{Q} signals	0.715	–	–	V
V_{ODIFF}	Differential Output Voltage (Q – \bar{Q}), Q = High (\bar{Q} – Q), \bar{Q} = High	$R_T = 100\Omega$ across Q and \bar{Q} signals	380	–	820	mV
V_{OCM}	Output Common-Mode Voltage	$R_T = 100\Omega$ across Q and \bar{Q} signals	1.000	1.250	1.375	V
V_{IDIFF}	Differential Input Voltage ⁽¹⁾⁽²⁾ (Q – \bar{Q}), Q = High (\bar{Q} – Q), \bar{Q} = High	Common-mode input voltage = 1.25V	100	–	1000	mV
V_{ICM}	Input Common-Mode Voltage	Differential input voltage = ± 350 mV	0.3	1.2	2.2	V

Notes:

1. Recommended input maximum voltage not to exceed $V_{CCO} + 0.2V$.
2. Recommended input minimum voltage not to go below $-0.5V$.

LVPECL DC Specifications (LVPECL_25)

These values are valid when driving a 100Ω differential load only, for example, a 100Ω resistor between the two receiver pins. The V_{OH} levels are 200 mV below standard LVPECL levels and are compatible with devices tolerant of lower common-mode ranges. Table 11 summarizes the DC output specifications of LVPECL. For more information on using LVPECL, see the *Virtex-4 FPGA User Guide*, Chapter 6, SelectIO Resources.

Table 11: LVPECL DC Specifications

Symbol	DC Parameter	Min	Typ	Max	Units
V_{OH}	Output High Voltage	$V_{CC} - 1.025$	1.545	$V_{CC} - 0.88$	V
V_{OL}	Output Low Voltage	$V_{CC} - 1.81$	0.795	$V_{CC} - 1.62$	V
V_{ICM}	Input Common-Mode Voltage	0.6		2.2	V
V_{IDIFF}	Differential Input Voltage ⁽¹⁾⁽²⁾	0.100		1.5	V

Notes:

1. Recommended input maximum voltage not to exceed $V_{CCO} + 0.2V$.
2. Recommended input minimum voltage not to go below $-0.5V$.

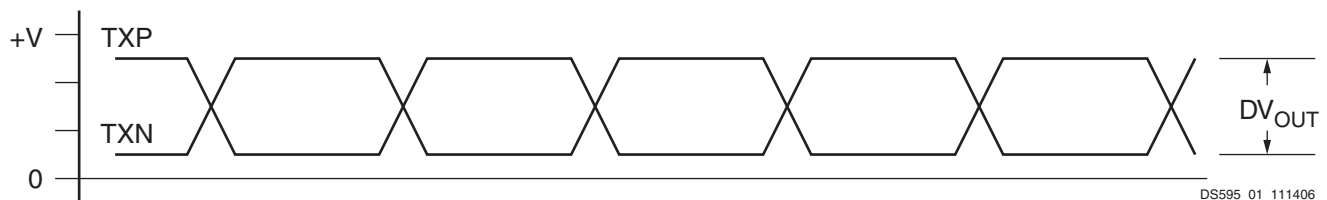


Figure 1: Single-Ended Output Voltage Swing

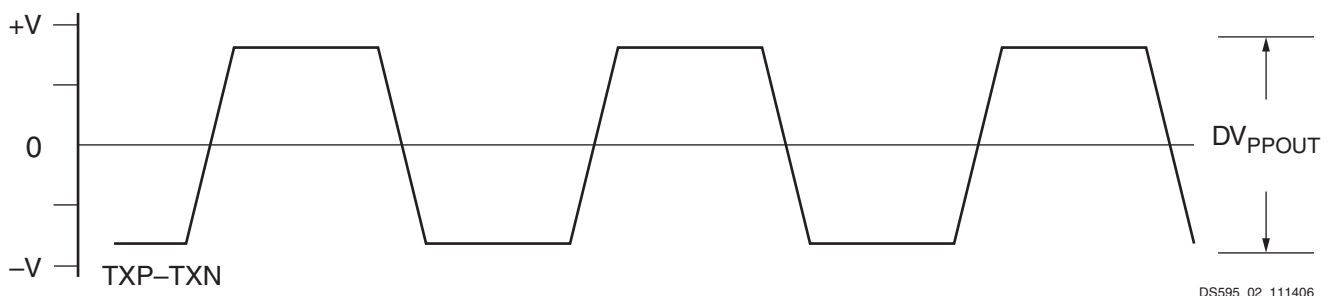


Figure 2: Peak-to-Peak Differential Output Voltage

Interface Performance Characteristics

Table 12: Interface Performances

Description	Speed Grade	
	-11	-10
Networking Applications		
SFI-4.1 (SDR LVDS Interface) ⁽¹⁾⁽⁷⁾	710 MHz	644 MHz
SPI-4.2 (DDR LVDS Interface) ⁽²⁾	1 Gb/s	800 Mb/s
Memory Interfaces		
DDR ⁽³⁾	426 Mb/s	426 Mb/s
DDR2 ⁽⁴⁾	510 Mb/s	510 Mb/s
QDR II SRAM ⁽⁵⁾	514 Mb/s	514 Mb/s
RLDRAM II ⁽⁶⁾	524 Mb/s	524 Mb/s

Notes:

1. Performance defined using design implementation described in application note [XAPP704](#), *Virtex-4 High-Speed SDR LVDS Transceiver*.
2. Performance defined using design implementation described in application note [XAPP700](#), *Dynamic Phase Alignment for Networking Applications* or [XAPP705](#), *Virtex-4 High-Speed DDR LVDS Transceiver*.
3. Performance defined using design implementation described in application note [XAPP709](#), *DDR SDRAM Controller Using Virtex-4 Devices*.
4. Performance defined using design implementation described in application note [XAPP702](#), *DDR2 Controller Using Virtex-4 Devices*.
5. Performance defined using design implementation described in application note [XAPP703](#), *QDR II SRAM Interface for Virtex-4 Devices*.
6. Performance defined using design implementation described in application note [XAPP710](#), *Synthesizable CIO DDR RLDRAM II Controller for Virtex-4 FPGAs*.
7. Maximum frequency of 500 MHz for operation beyond industrial temperature range.

Switching Characteristics

Switching characteristics are specified on a per-speed grade basis and can be designated as Advance, Preliminary, or Production. Each designation is defined as follows:

Advance Product Specification

These specifications are based on simulations only and are typically available soon after device design specifications are frozen. Although speed grades with this designation are considered relatively stable and conservative, some under-reporting might still occur.

Preliminary Product Specification

These specifications are based on complete ES (engineering sample) silicon characterization. Devices and speed grades with this designation are intended to give a better indication of the expected performance of production silicon. The probability of under-reporting delays is greatly reduced as compared to Advance data.

Production Product Specification

These specifications are released once enough production silicon of a particular device family member has been characterized to provide full correlation between specifications and devices over numerous production lots. There is no under-reporting of delays, and customers receive formal notification of any subsequent changes. Typically, the slowest speed grades transition to Production before faster speed grades.

Speed Specification Designations by Device

Since individual family members are produced at different times, the migration from one category to another depends completely on the status of the fabrication process for each device.

All specifications are always representative of worst-case supply voltage and junction temperature conditions.

[Table 13](#) correlates the current status of each Virtex-4Q device on a per speed grade basis.

Table 13: Virtex-4Q Device Speed Grade Designations

Device	Speed Grade Designations		
	Advance	Preliminary	Production
XQ4VLX25			-10(M)
XQ4VLX40			-10(M), -10(I)
XQ4VLX60			-10(M)
XQ4VLX80			-11(I)
XQ4VLX100			-11(I), -10(I)
XQ4VLX160			-10(I)
XQ4VSX55			-10(M)
XQ4VFX60			-10(M), -10(I)
XQ4VFX100			-11(I)

Testing of Switching Characteristics

All devices are 100% functionally tested. Internal timing parameters are derived from measuring internal test patterns. Listed below are representative values. For more specific, more precise, and worst-case guaranteed data, use the values reported by the static timing analyzer (TRCE in the Xilinx Development System) and back-annotate to the simulation net list. Unless otherwise noted, values apply to all Virtex-4 FPGAs.

Production Silicon and ISE Software Status

Table 14 lists the production released Virtex-4Q family member, speed grade, and the minimum corresponding supported speed specification version and ISE® software revisions. The ISE software and speed specifications listed are the minimum releases required for production. All subsequent releases of software and speed specifications are valid.

Table 14: Virtex-5 Device Production Software and Speed Specification Release

Device	Speed Grade Designations		
	-11(I)	-10(I)	-10(M)
XQ4VLX25	N/A	N/A	ISE 9.2 v1.67
XQ4VLX40	N/A	ISE 9.2 v1.67	ISE 9.2 v1.67
XQ4VLX60	N/A	N/A	ISE 9.2 v1.67
XQ4VLX80	ISE 14.1 v1.71	N/A	N/A
XQ4VLX100	ISE 14.1 v1.71	ISE 9.2 v1.67	N/A
XQ4VLX160	N/A	ISE 9.2 v1.67	N/A
XQ4VSX55	N/A	N/A	ISE 9.2 v1.67
XQ4VFX60	N/A	ISE 9.2 v1.67	ISE 9.2 v1.67
XQ4VFX100	ISE 14.1 v1.71	N/A	N/A

PowerPC Switching Characteristics

Consult [UG018](#), *PowerPC® 405 Processor Block Reference Guide* for further information.

Table 15: PowerPC 405 Processor Clocks Absolute AC Characteristics

Description	Speed Grade				Units
	-11		-10		
	Min	Max	Min	Max	
Characteristics when APU Not Used					
CPMC405CLOCK frequency ⁽¹⁾⁽⁴⁾	0	400	0	350	MHz
CPMDCRCLK ⁽³⁾	0	400	0	350	MHz
CPMFCMCLK ⁽³⁾	–	–	–	–	MHz
JTAGC405TCK frequency ⁽²⁾	0	200	0	175	MHz
PLBCLK ⁽³⁾	0	400	0	350	MHz
BRAMDSOCMCLK ⁽³⁾	0	400	0	350	MHz
BRAMISOCMCLK ⁽³⁾	0	400	0	350	MHz
Characteristics when APU Used					
CPMC405CLOCK frequency ⁽¹⁾⁽⁴⁾	0	275	0	233	MHz
CPMDCRCLK ⁽³⁾	0	275	0	233	MHz
CPMFCMCLK ⁽³⁾	0	275	0	233	MHz
JTAGC405TCK frequency ⁽²⁾	0	137.5	0	116.5	MHz
PLBCLK ⁽³⁾	0	275	0	233	MHz
BRAMDSOCMCLK ⁽³⁾	0	275	0	233	MHz
BRAMISOCMCLK ⁽³⁾	0	275	0	233	MHz

Notes:

1. Worst-case DCM output clock jitter is included in these specifications.
2. The theoretical maximum frequency of this clock is one-half the CPMC405CLOCK. However, the achievable maximum is system dependent, and will be much less.
3. The theoretical maximum frequency of these clocks is equal to the CPMC405CLOCK. Integer clock ratios are required for the CPMC405CLOCK and BRAMDSOCMCLK, CPMC405CLOCK and BRAMISOCMCLK, CPMC405CLOCK and CPMDCRCLK, CPMC405CLOCK and CPMFCMCLK, and CPMC405CLOCK and PLBCLK. The integer ratios can be different for each interface. However, the achievable maximum is system dependent.
4. Maximum operating frequency of CPMC405CLOCK is specified with the input pin TIEC405DISOPERANDFWD connected to a logic 1.

Table 16: Processor Block Switching Characteristics

Description	Symbol	Speed Grade		Units
		-11	-10	
Setup and Hold Relative to Clock (CPMC405CLOCK)				
Clock and Power Management control inputs	T _{PPCDCK_CORECKI} T _{PPCCKD_CORECKI}	0.65/0.20	0.74/0.23	ns Min
Reset control inputs	T _{PPCDCK_RSTCHIP} T _{PPCCKD_RSTCHIP}	0.65/0.20	0.74/0.23	ns Min
Debug control inputs	T _{PPCDCK_EXBUSHAK} T _{PPCCKD_EXBUSHAK}	0.65/0.20	0.74/0.23	ns Min
Trace control inputs	T _{PPCDCK_TRCDIS} T _{PPCCKD_TRCDIS}	0.65/0.20	0.74/0.23	ns Min
External Interrupt Controller control inputs	T _{PPCDCK_CINPIRQ} T _{PPCCKD_CINPIRQ}	1.15/0.20	1.40/0.23	ns Min
Clock to Out				

Table 16: Processor Block Switching Characteristics (Cont'd)

Description	Symbol	Speed Grade		Units
		-11	-10	
Clock and Power Management control outputs	T _{PPCCKO_CORESLP}	1.51	1.74	ns Max
Reset control outputs	T _{PPCCKO_RSTCHIP}	1.59	1.83	ns Max
Debug control outputs	T _{PPCCKO_DBGLDAPU}	1.48	1.70	ns Max
Trace control outputs	T _{PPCCKO_TRCCYCLE}	1.68	1.83	ns Max
Clock				
CPMC405CLOCK minimum pulse width, High	T _{CPWH}	1.25	1.43	ns Min
CPMC405CLOCK minimum pulse width, Low	T _{CPWL}	1.25	1.43	ns Min

Table 17: Processor Block PLB Switching Characteristics

Description	Symbol	Speed Grade		Units
		-11	-10	
Setup and Hold Relative to Clock (PLBCLK)				
Processor Local Bus (ICU/DCU) control inputs	T _{PPCDCK_ICUBUSY} T _{PPCCKD_ICUBUSY}	0.66/0.20	0.76/0.23	ns Min
Processor Local Bus (ICU/DCU) data inputs	T _{PPCDCK_ICURDDB} T _{PPCCKD_ICURDDB}	1.00/0.20	1.15/0.23	ns Min
Clock to Out				
Processor Local Bus (ICU/DCU) control outputs	T _{PPCCKO_DCUABORT}	1.78	2.05	ns Max
Processor Local Bus (ICU/DCU) address bus outputs	T _{PPCCKO_ICUABUS}	1.85	2.13	ns Max
Processor Local Bus (ICU/DCU) data bus outputs	T _{PPCCKO_DCUWRDBUS}	2.24	2.57	ns Max

Table 18: Processor Block JTAG Switching Characteristics

Description	Symbol	Speed Grade		Units
		-11	-10	
Setup and Hold Relative to Clock (JTAGC405TCK)				
JTAG control inputs	T _{PPCDCK_JTGTDI} T _{PPCCKD_JTGTDI}	1.29/0.20	1.48/0.23	ns Min
JTAG reset input	T _{PPCDCK_JTGTRSTN} T _{PPCCKD_JTGTRSTN}	0.65/0.20	0.74/0.23	ns Min
Clock to Out				
JTAG control outputs	T _{PPCCKO_JTGTO}	1.79	2.14	ns Max

Table 19: PowerPC 405 Data-Side On-Chip Memory Switching Characteristics

Description	Symbol	Speed Grade		Units
		-11	-10	
Setup and Hold Relative to Clock (BRAMDSOCCLK)				
Data-Side On-Chip Memory data bus inputs	T _{PPCDCK_DSOCMRDDB} T _{PPCCKD_DSOCMRDDB}	0.65/0.20	0.74/0.23	ns Min
Clock to Out				
Data-Side On-Chip Memory control outputs	T _{PPCCKO_BRAMBWR}	2.30	2.65	ns Max
Data-Side On-Chip Memory address bus outputs	T _{PPCCKO_BRAMABUS}	2.30	2.65	ns Max
Data-Side On-Chip Memory data bus outputs	T _{PPCCKO_IBRAMWRDBUS01}	1.79	2.06	ns Max

Table 20: PowerPC 405 Instruction-Side On-Chip Memory Switching Characteristics

Description	Symbol	Speed Grade		Units
		-11	-10	
Setup and Hold Relative to Clock (BRAMISOCCLK)				
Instruction-Side On-Chip Memory data bus inputs	T _{PPCDCK_ISOCMRDDB} T _{PPCCKD_ISOCMRDDB}	0.82/0.20	0.94/0.23	ns Min
Clock to Out				
Instruction-Side On-Chip Memory control outputs	T _{PPCCKO_IBRAMEN}	3.37	3.88	ns Max
Instruction-Side On-Chip Memory address bus outputs	T _{PPCCKO_IBRAMRDABUS}	1.85	2.13	ns Max
Instruction-Side On-Chip Memory data bus outputs	T _{PPCCKO_IBRAMWRDBUS}	1.86	2.14	ns Max

Table 21: Processor Block DCR Bus Switching Characteristics

Description	Symbol	Speed Grade		Units
		-11	-10	
Setup and Hold Relative to Clock (CPMDRCLOCK)				
Device Control Register Bus control inputs	T _{PPCDCK_EXDCRACK} T _{PPCCKD_EXDCRACK}	0.13/0.17	0.15/0.19	ns Min
Device Control Register Bus data inputs	T _{PPCDCK_EXDCRDBUSI} T _{PPCCKD_EXDCRDBUSI}	0.57/0.16	1.02/0.27	ns Min
Clock to Out				
Device Control Register Bus control outputs	T _{PPCCKO_EXDCRRD}	1.35	1.54	ns Max
Device Control Register Bus address bus outputs	T _{PPCCKO_EXDCRABUS}	1.45	1.66	ns Max
Device Control Register Bus data bus outputs	T _{PPCCKO_EXDCRDBUSO}	1.45	1.67	ns Max

Table 22: Processor Block APU Interface Switching Characteristics

Description	Symbol	Speed Grade		Units
		-11	-10	
Setup and Hold Relative to Clock (CPMDFCMCLOCK)				
APU bus control inputs	T _{PPCDCK_DCDCREN} T _{PPCCKD_DCDCREN}	0.36/0.20	0.42/0.23	ns Min
APU bus data inputs	T _{PPCDCK_RESULT} T _{PPCCKD_RESULT}	0.67/0.20	0.78/0.23	ns Min
Clock to Out				
APU bus control outputs	T _{PPCCKO_APUFCMDEC}	1.75	2.00	ns Max
APU bus data outputs	T _{PPCCKO_RADATA}	1.75	2.00	ns Max

IOB Pad Input/Output/3-State Switching Characteristics

Table 23, page 13 summarizes the values of standard-specific data input delay adjustments, output delays terminating at pads (based on standard and 3-state delays).

T_{IOPI} is described as the delay from IOB pad through the input buffer to the I-pin of an IOB pad. The delay varies depending on the capability of the SelectIO™ input buffer.

T_{IOOP} is described as the delay from the O pin to the IOB pad through the output buffer of an IOB pad. The delay varies depending on the capability of the SelectIO output buffer.

T_{IOTP} is described as the delay from the T pin to the IOB pad through the output buffer of an IOB pad, when 3-state is disabled. The delay varies depending on the SelectIO capability of the output buffer.

Table 25, page 18 summarizes the value of T_{IOTPHZ} . T_{IOTPHZ} is described as the delay from the T pin to the IOB pad through the output buffer of an IOB pad, when 3-state is enabled (for example, a high-impedance state).

Table 23: IOB Switching Characteristics⁽¹⁾⁽²⁾

IOSTANDARD Attribute ⁽¹⁾	Speed Grade						Units
	-11			-10			
	T_{IOPI}	T_{IOOP}	T_{IOTP}	T_{IOPI}	T_{IOOP}	T_{IOTP}	
LVDS_25	1.15	1.71	1.71	1.28	1.85	1.85	ns
RSDS_25	1.15	1.71	1.71	1.28	1.85	1.85	ns
LVDSEXT_25	1.16	1.75	1.75	1.30	1.91	1.91	ns
LDT_25	1.15	1.68	1.68	1.28	1.82	1.82	ns
BLVDS_25	1.15	2.15	2.15	1.28	2.34	2.34	ns
ULVDS_25	1.15	1.68	1.68	1.28	1.83	1.83	ns
PCI33_3 (PCI®, 33 MHz, 3.3V)	0.87	2.76	2.76	0.97	3.02	3.02	ns
PCI66_3 (PCI, 66 MHz, 3.3V)	0.87	2.46	2.46	0.97	2.72	2.72	ns
PCI-X (PCI-X)	0.87	2.21	2.21	0.97	2.25	2.25	ns
GTL	1.47	1.87	1.87	1.63	2.03	2.03	ns
GTLP	1.51	1.87	1.87	1.68	2.03	2.03	ns
HSTL_I	1.47	2.16	2.16	1.64	2.35	2.35	ns
HSTL_II	1.47	1.96	1.96	1.64	2.13	2.13	ns
HSTL_III	1.47	2.04	2.04	1.64	2.22	2.22	ns
HSTL_IV	1.47	1.87	1.87	1.64	2.03	2.03	ns
HSTL_I_18	1.44	2.03	2.03	1.60	2.21	2.21	ns
HSTL_II_18	1.44	1.98	1.98	1.60	2.16	2.16	ns
HSTL_III_18	1.44	1.93	1.93	1.60	2.09	2.09	ns
HSTL_IV_18	1.44	1.89	1.89	1.60	2.06	2.06	ns
SSTL2_I	1.51	2.23	2.23	1.68	2.43	2.43	ns
SSTL2_II	1.51	1.98	1.98	1.68	2.16	2.16	ns
LVTTL, Slow, 2 mA	0.87	6.37	6.37	0.97	7.03	7.03	ns
LVTTL, Slow, 4 mA	0.87	4.57	4.57	0.97	5.04	5.04	ns
LVTTL, Slow, 6 mA	0.87	4.46	4.46	0.97	4.91	4.91	ns
LVTTL, Slow, 8 mA	0.87	4.46	4.46	0.97	4.91	4.91	ns
LVTTL, Slow, 12 mA	0.87	3.61	3.61	0.97	3.96	3.96	ns
LVTTL, Slow, 16 mA	0.87	3.61	3.61	0.97	3.46	3.46	ns

Table 23: IOB Switching Characteristics⁽¹⁾⁽²⁾ (Cont'd)

IOSTANDARD Attribute ⁽¹⁾	Speed Grade						Units
	-11			-10			
	T _{IOPI}	T _{IOOP}	T _{IOTP}	T _{IOPI}	T _{IOOP}	T _{IOTP}	
LVTTTL, Slow, 24 mA	0.87	2.85	2.85	0.97	3.12	3.12	ns
LVTTTL, Fast, 2 mA	0.87	4.41	4.41	0.97	4.86	4.86	ns
LVTTTL, Fast, 4 mA	0.87	3.16	3.16	0.97	3.46	3.46	ns
LVTTTL, Fast, 6 mA	0.87	2.74	2.74	0.97	3.00	3.00	ns
LVTTTL, Fast, 8 mA	0.87	2.55	2.55	0.97	2.79	2.79	ns
LVTTTL, Fast, 12 mA	0.87	2.26	2.26	0.97	2.47	2.47	ns
LVTTTL, Fast, 16 mA	0.87	2.26	2.26	0.97	2.47	2.47	ns
LVTTTL, Fast, 24 mA	0.87	2.02	2.02	0.97	2.20	2.20	ns
LVCMOS33, Slow, 2 mA	0.87	7.88	7.88	0.97	8.73	8.73	ns
LVCMOS33, Slow, 4 mA	0.87	5.52	5.52	0.97	6.09	6.09	ns
LVCMOS33, Slow, 6 mA	0.87	4.54	4.54	0.97	5.00	5.00	ns
LVCMOS33, Slow, 8 mA	0.87	3.59	3.59	0.97	3.95	3.95	ns
LVCMOS33, Slow, 12 mA	0.87	3.11	3.11	0.97	3.42	3.42	ns
LVCMOS33, Slow, 16 mA	0.87	2.28	2.28	0.97	2.49	2.49	ns
LVCMOS33, Slow, 24 mA	0.87	2.28	2.28	0.97	2.49	2.49	ns
LVCMOS33, Fast, 2 mA	0.87	6.73	6.73	0.97	7.44	7.44	ns
LVCMOS33, Fast, 4 mA	0.87	3.93	3.93	0.97	4.33	4.33	ns
LVCMOS33, Fast, 6 mA	0.87	3.23	3.23	0.97	3.55	3.55	ns
LVCMOS33, Fast, 8 mA	0.87	2.25	2.25	0.97	2.46	2.46	ns
LVCMOS33, Fast, 12 mA	0.87	2.08	2.08	0.97	2.27	2.27	ns
LVCMOS33, Fast, 16 mA	0.87	1.91	1.91	0.97	2.08	2.08	ns
LVCMOS33, Fast, 24 mA	0.87	1.91	1.91	0.97	2.08	2.08	ns
LVCMOS25, Slow, 2 mA	0.80	5.34	5.34	0.88	5.89	5.89	ns
LVCMOS25, Slow, 4 mA	0.80	4.56	4.56	0.88	5.02	5.02	ns
LVCMOS25, Slow, 6 mA	0.80	3.92	3.92	0.88	4.31	4.31	ns
LVCMOS25, Slow, 8 mA	0.80	3.92	3.92	0.88	4.31	4.31	ns
LVCMOS25, Slow, 12 mA	0.80	3.19	3.19	0.88	3.50	3.50	ns
LVCMOS25, Slow, 16 mA	0.80	3.02	3.02	0.88	3.31	3.31	ns
LVCMOS25, Slow, 24 mA	0.80	2.54	2.54	0.88	2.77	2.77	ns
LVCMOS25, Fast, 2 mA	0.80	3.54	3.54	0.88	3.89	3.89	ns
LVCMOS25, Fast, 4 mA	0.80	2.92	2.92	0.88	3.19	3.19	ns
LVCMOS25, Fast, 6 mA	0.80	2.57	2.57	0.88	2.81	2.81	ns
LVCMOS25, Fast, 8 mA	0.80	2.31	2.31	0.88	2.52	2.52	ns
LVCMOS25, Fast, 12 mA	0.80	2.23	2.23	0.88	2.43	2.43	ns
LVCMOS25, Fast, 16 mA	0.80	2.03	2.03	0.88	2.21	2.21	ns
LVCMOS25, Fast, 24 mA	0.80	1.96	1.96	0.88	2.13	2.13	ns
LVCMOS18, Slow, 2 mA	1.12	5.34	5.34	1.25	5.89	5.89	ns
LVCMOS18, Slow, 4 mA	1.12	3.95	3.95	1.25	4.35	4.35	ns

Table 23: IOB Switching Characteristics⁽¹⁾⁽²⁾ (Cont'd)

IOSTANDARD Attribute ⁽¹⁾	Speed Grade						Units
	-11			-10			
	T _{IOPI}	T _{IOOP}	T _{IOTP}	T _{IOPI}	T _{IOOP}	T _{IOTP}	
LVC MOS18, Slow, 6 mA	1.12	3.64	3.64	1.25	4.00	4.00	ns
LVC MOS18, Slow, 8 mA	1.12	3.42	3.42	1.25	3.76	3.76	ns
LVC MOS18, Slow, 12 mA	1.12	3.41	3.41	1.25	3.74	3.74	ns
LVC MOS18, Slow, 16 mA	1.12	3.24	3.24	1.25	3.55	3.55	ns
LVC MOS18, Fast, 2 mA	1.12	3.54	3.54	1.25	3.89	3.89	ns
LVC MOS18, Fast, 4 mA	1.12	2.75	2.75	1.25	3.02	3.02	ns
LVC MOS18, Fast, 6 mA	1.12	2.49	2.49	1.25	2.72	2.72	ns
LVC MOS18, Fast, 8 mA	1.12	2.31	2.31	1.25	2.52	2.52	ns
LVC MOS18, Fast, 12 mA	1.12	2.17	2.17	1.25	2.36	2.36	ns
LVC MOS18, Fast, 16 mA	1.12	2.09	2.09	1.25	2.27	2.27	ns
LVC MOS15, Slow, 2 mA	1.20	5.99	5.99	1.34	6.61	6.61	ns
LVC MOS15, Slow, 4 mA	1.20	4.70	4.70	1.34	4.88	4.88	ns
LVC MOS15, Slow, 6 mA	1.20	3.87	3.87	1.34	4.26	4.26	ns
LVC MOS15, Slow, 8 mA	1.20	3.87	3.87	1.34	4.26	4.26	ns
LVC MOS15, Slow, 12 mA	1.20	3.43	3.43	1.34	3.77	3.77	ns
LVC MOS15, Slow, 16 mA	1.20	3.21	3.21	1.34	3.53	3.53	ns
LVC MOS15, Fast, 2 mA	1.20	3.79	3.79	1.34	4.17	4.17	ns
LVC MOS15, Fast, 4 mA	1.20	3.03	3.03	1.34	3.32	3.32	ns
LVC MOS15, Fast, 6 mA	1.20	2.69	2.69	1.34	2.94	2.94	ns
LVC MOS15, Fast, 8 mA	1.20	2.48	2.48	1.34	2.71	2.71	ns
LVC MOS15, Fast, 12 mA	1.20	2.29	2.29	1.34	2.50	2.50	ns
LVC MOS15, Fast, 16 mA	1.20	2.23	2.23	1.34	2.43	2.43	ns
LVDCI_33	0.87	2.86	2.86	0.97	3.13	3.13	ns
LVDCI_25	0.80	2.76	2.76	0.88	3.02	3.02	ns
LVDCI_18	1.12	2.69	2.69	1.25	2.95	2.95	ns
LVDCI_15	1.20	2.68	2.68	1.34	2.93	2.93	ns
LVDCI_DV2_25	0.80	2.08	2.08	0.88	2.27	2.27	ns
LVDCI_DV2_18	1.12	2.09	2.09	1.25	2.28	2.28	ns
LVDCI_DV2_15	1.20	2.36	2.36	1.34	2.58	2.58	ns
GTL_DCI	1.36	1.87	1.87	1.51	2.03	2.03	ns
GTL_P_DCI	1.11	1.87	1.87	1.23	2.03	2.03	ns
HSTL_I_DCI	1.47	2.16	2.16	1.64	2.35	2.35	ns
HSTL_II_DCI	1.47	1.96	1.96	1.64	2.13	2.13	ns
HSTL_III_DCI	1.47	2.04	2.04	1.64	2.22	2.22	ns
HSTL_IV_DCI	1.47	1.87	1.87	1.64	2.03	2.03	ns
HSTL_I_DCI_18	1.44	2.03	2.03	1.60	2.21	2.21	ns
HSTL_II_DCI_18	1.44	1.98	1.98	1.60	2.16	2.16	ns
HSTL_III_DCI_18	1.44	1.93	1.93	1.60	2.09	2.09	ns

Table 23: IOB Switching Characteristics⁽¹⁾⁽²⁾ (Cont'd)

IOSTANDARD Attribute ⁽¹⁾	Speed Grade						Units
	-11			-10			
	T _{IOPI}	T _{IOOP}	T _{IOTP}	T _{IOPI}	T _{IOOP}	T _{IOTP}	
HSTL_IV_DCI_18	1.44	1.89	1.89	1.60	2.06	2.06	ns
SSTL2_I_DCI	1.51	2.25	2.25	1.68	2.46	2.46	ns
SSTL2_II_DCI	1.51	2.24	2.24	1.68	2.45	2.45	ns
LVPECL_25	1.59	1.61	1.61	1.77	1.74	1.74	ns
SSTL18_I	1.51	2.33	2.33	1.68	2.54	2.54	ns
SSTL18_II	1.51	2.06	2.06	1.68	2.24	2.24	ns
SSTL18_I_DCI	1.51	2.12	2.12	1.68	2.32	2.32	ns
SSTL18_II_DCI	1.51	2.00	2.00	1.68	2.18	2.18	ns

Notes:

1. The I/O standard is selected in the Xilinx ISE® software using the IOSTANDARD attribute.
2. All I/O timing specifications are measured with V_{CCO} at -5% from nominal.

Table 24: T_{IOOP} and T_{IOTP} Offset for 125°C Operation

IOSTANDARD Attribute	Speed Grade			Units
	-10			
	I-Grade	M-Grade	Delta	
LVDS	1.85	2.23	0.38	ns
RSDS	1.85	2.23	0.38	ns
LVDSEXT	1.91	2.25	0.34	ns
LDT	1.82	2.23	0.41	ns
PCI33_3	3.02	3.26	0.24	ns
PCI66_3	2.72	3.26	0.54	ns
PCIX	2.25	2.49	0.24	ns
GTL	2.03	2.27	0.24	ns
GTLP	2.03	2.25	0.22	ns
HSTL_I	2.35	2.54	0.19	ns
HSTL_II	2.13	2.47	0.34	ns
HSTL_III	2.22	2.55	0.33	ns
HSTL_IV	2.03	2.43	0.40	ns
HSTL_I_18	2.21	2.43	0.22	ns
HSTL_II_18	2.16	2.39	0.23	ns
HSTL_III_18	2.09	2.40	0.31	ns
HSTL_IV_18	2.06	2.38	0.32	ns
SSTL2_I	2.43	2.46	0.03	ns
SSTL2_II	2.16	2.27	0.11	ns
LVTTTL_S2	7.03	9.95	2.92	ns
LVTTTL_S4	5.04	7.84	2.80	ns
LVTTTL_S6	4.91	6.67	1.76	ns
LVTTTL_S8	4.91	6.40	1.49	ns

Table 24: T_{IOOP} and T_{IOTP} Offset for 125°C Operation (Cont'd)

IOSTANDARD Attribute	Speed Grade			Units
	-10			
	I-Grade	M-Grade	Delta	
LVTTL_S12	3.96	4.87	0.91	ns
LVTTL_S16	3.46	4.42	0.96	ns
LVTTL_S24	3.12	3.24	0.12	ns
LVTTL_F2	4.86	8.44	3.58	ns
LVTTL_F4	3.46	6.41	2.95	ns
LVTTL_F6	3.00	4.76	1.76	ns
LVTTL_F8	2.79	3.97	1.18	ns
LVTTL_F12	2.47	2.92	0.45	ns
LVTTL_F16	2.47	2.93	0.46	ns
LVTTL_F24	2.20	2.87	0.67	ns
LVC MOS33_S2	8.73	11.43	2.70	ns
LVC MOS33_S4	6.09	8.56	2.47	ns
LVC MOS33_S6	5.00	7.27	2.27	ns
LVC MOS33_S8	3.95	6.35	2.40	ns
LVC MOS33_S12	3.42	4.74	1.32	ns
LVC MOS33_S16	2.49	4.56	2.07	ns
LVC MOS33_S24	2.49	3.06	0.57	ns
LVC MOS33_F2	7.44	10.18	2.74	ns
LVC MOS33_F4	4.33	6.18	1.85	ns
LVC MOS33_F6	3.55	5.53	1.98	ns
LVC MOS33_F8	2.46	4.47	2.01	ns
LVC MOS33_F12	2.27	3.22	0.95	ns
LVC MOS33_F16	2.08	2.74	0.66	ns
LVC MOS33_F24	2.08	2.61	0.53	ns
LVC MOS25_S2	5.89	8.57	2.68	ns
LVC MOS25_S4	5.02	6.44	1.42	ns
LVC MOS25_S6	4.31	6.00	1.69	ns
LVC MOS25_S8	4.31	5.24	0.93	ns
LVC MOS25_S12	3.50	4.30	0.80	ns
LVC MOS25_S16	3.31	3.95	0.64	ns
LVC MOS25_S24	2.77	2.64	-0.13	ns
LVC MOS25_F2	3.89	7.97	4.08	ns
LVC MOS25_F4	3.19	4.99	1.80	ns
LVC MOS25_F6	2.81	3.92	1.11	ns
LVC MOS25_F8	2.52	3.29	0.77	ns
LVC MOS25_F12	2.43	2.43	0.00	ns
LVC MOS25_F16	2.21	2.39	0.18	ns
LVC MOS25_F24	2.13	2.39	0.26	ns

Table 24: T_{IOOP} and T_{IOTP} Offset for 125°C Operation (Cont'd)

IOSTANDARD Attribute	Speed Grade			Units
	-10			
	I-Grade	M-Grade	Delta	
LVC MOS18_S2	5.89	8.68	2.79	ns
LVC MOS18_S4	4.35	7.31	2.96	ns
LVC MOS18_S6	4.00	5.66	1.66	ns
LVC MOS18_S8	3.76	5.11	1.35	ns
LVC MOS18_S12	3.74	4.59	0.85	ns
LVC MOS18_S16	3.55	3.89	0.34	ns
LVC MOS18_F2	3.89	8.34	4.45	ns
LVC MOS18_F4	3.02	5.99	2.97	ns
LVC MOS18_F6	2.72	4.35	1.63	ns
LVC MOS18_F8	2.52	3.66	1.14	ns
LVC MOS18_F12	2.36	2.80	0.44	ns
LVC MOS18_F16	2.27	2.70	0.43	ns
LVC MOS15_S2	6.61	9.21	2.60	ns
LVC MOS15_S4	4.88	7.75	2.87	ns
LVC MOS15_S6	4.26	6.14	1.88	ns
LVC MOS15_S8	4.26	6.18	1.92	ns
LVC MOS15_S12	3.77	4.77	1.00	ns
LVC MOS15_S16	3.53	4.07	0.54	ns
LVC MOS15_F2	4.17	8.32	4.15	ns
LVC MOS15_F4	3.32	6.53	3.21	ns
LVC MOS15_F6	2.94	4.69	1.75	ns
LVC MOS15_F8	2.71	3.90	1.19	ns
LVC MOS15_F12	2.50	2.92	0.42	ns
LVC MOS15_F16	2.43	2.84	0.41	ns
SSTL18_I	2.54	2.44	-0.10	ns
SSTL18_II	2.24	2.42	0.18	ns

Table 25: IOB 3-State On Output Switching Characteristics (T_{IOTPHZ})

Symbol	Description	Speed Grade		Units
		-11	-10	
T _{IOTPHZ}	T input to Pad high-impedance	1.01	1.12	ns

Ethernet MAC Switching Characteristics

Consult [UG074](#), Virtex-4 FPGA Embedded Tri-Mode Ethernet MAC User Guide for further information.

Table 26: Maximum Ethernet MAC Performance

Description	Speed Grade		Units
	-11	-10	
Ethernet MAC Maximum Performance	10/100/1000		Mb/s

Input/Output Logic Switching Characteristics

Table 27: ILOGIC Switching Characteristics

Symbol	Description	Speed Grade		Units
		-11	-10	
Setup/Hold				
T_{ICE1CK}/T_{ICKCE1}	CE1 pin setup/hold with respect to CLK	0.66/-0.23	0.79/-0.23	ns
T_{ICECK}/T_{ICKCE}	DLYCE pin setup/hold with respect to CLKDIV	0.19/0.13	0.23/0.16	ns
T_{IRSTCK}/T_{ICKRST}	DLYRST pin setup/hold with respect to CLKDIV	-0.02/0.45	-0.02/0.54	ns
T_{IINCCK}/T_{ICKINC}	DLYINC pin setup/hold with respect to CLKDIV	0.01/0.43	0.01/0.51	ns
T_{ISRCK}/T_{ICKSR}	SR/REV pin setup/hold with respect to CLK	1.33/-0.56	1.59/-0.56	ns
T_{IDOCK}/T_{IOCKD}	D pin setup/hold with respect to CLK without Delay	0.28/-0.10	0.34/-0.10	ns
T_{IDOCKD}/T_{IOCKDD}	D pin setup/hold with respect to CLK (IOBDELAY_TYPE = DEFAULT)	7.63/-5.99	8.84/-5.99	ns
	D pin setup/hold with respect to CLK (IOBDELAY_TYPE = FIXED, IOBDELAY_VALUE = 0)	0.87/-0.63	1.09/-0.63	ns
Combinatorial				
T_{IDI}	D pin to O pin propagation delay, no Delay	0.20	0.24	ns
T_{IDID}	D pin to O pin propagation delay (IOBDELAY_TYPE = DEFAULT)	6.91	7.96	ns
	D pin to O pin propagation delay (IOBDELAY_TYPE = FIXED, IOBDELAY_VALUE = 0)	0.79	0.99	ns
Sequential Delays				
T_{IDLO}	D pin to Q1 pin using flip-flop as a latch without Delay	0.59	0.71	ns
T_{IDL0D}	D pin to Q1 pin using flip-flop as a latch (IOBDELAY_TYPE = DEFAULT)	7.94	9.21	ns
	D pin to Q1 pin using flip-flop as a latch (IOBDELAY_TYPE = FIXED, IOBDELAY_VALUE = 0)	1.18	1.45	ns
T_{ICKQ}	CLK to Q outputs	0.60	0.72	ns
T_{ICE1Q}	CE1 pin to Q1 using flip-flop as a latch, propagation delay	1.06	1.27	ns
T_{RQ}	SR/REV pin to OQ/TQ out	2.03	2.44	ns
T_{GSRQ}	Global Set/Reset to Q outputs	1.73	2.03	ns
Set/Reset				
T_{RPW}	Minimum Pulse Width, SR/REV inputs	0.59	0.70	ns, Min

Table 28: OLOGIC Switching Characteristics

Symbol	Description	Speed Grade		Units
		-11	-10	
Setup/Hold				
T_{ODCK}/T_{OCKD}	D1/D2 pins setup/hold with respect to CLK	0.62/-0.22	0.75/-0.22	ns
T_{OOCECK}/T_{OCKOCE}	OCE pin setup/hold with respect to CLK	0.64/-0.33	0.77/-0.33	ns
T_{OSRCK}/T_{OCKSR}	SR/REV pin setup/hold with respect to CLK	1.18/-0.55	1.42/-0.55	ns
T_{OTCK}/T_{OCKT}	T1/T2 pins setup/hold with respect to CLK	0.62/-0.22	0.75/-0.22	ns
T_{OTCECK}/T_{OCKTCE}	TCE pin setup/hold with respect to CLK	0.64/-0.33	0.77/-0.33	ns
Combinatorial				
T_{ODQ}	D1 to OQ out	0.65	0.76	ns
T_{OTQ}	T1 to TQ out	0.65	0.76	ns
Sequential Delays				
T_{IOSRON}	REV pin to TQ out	1.37	1.64	ns
T_{OCKQ}	CLK to OQ/TQ out	0.49	0.59	ns
T_{RQ}	SR/REV pin to OQ/TQ out	1.37	1.64	ns
T_{GSRQ}	Global Set/Reset to Q outputs	1.73	2.03	ns
Set/Reset				
T_{RPW}	Minimum Pulse Width, SR/REV inputs	0.59	0.70	ns Min

Input Serializer/Deserializer Switching Characteristics

Table 29: ISERDES Switching Characteristics

Symbol	Description	Speed Grade		Units
		-11	-10	
Setup/Hold for Control Lines				
$T_{ISCK_BITSLIP} / T_{ISCKC_BITSLIP}$	BITSLIP pin setup/hold with respect to CLKDIV	0.34/-0.16	0.40/-0.13	ns
$T_{ISCK_CE} / T_{ISCKC_CE}^{(2)}$	CE pin setup/hold with respect to CLK (for CE1)	0.57/-0.30	0.69/-0.25	ns
$T_{ISCK_CE2} / T_{ISCKC_CE2}^{(2)}$	CE pin setup/hold with respect to CLKDIV (for CE2)	0.14/-0.03	0.16/-0.02	ns
$T_{ISCK_DLYCE} / T_{ISCKC_DLYCE}$	DLYCE pin setup/hold with respect to CLKDIV	0.19/0.13	0.23/0.16	ns
$T_{ISCK_DLYINC} / T_{ISCKC_DLYINC}$	DLYINC pin setup/hold with respect to CLKDIV	0.01/0.43	0.01/0.51	ns
$T_{ISCK_DLYRST} / T_{ISCKC_DLYRST}$	DLYRST pin setup/hold with respect to CLKDIV	-0.02/0.45	-0.02/0.54	ns
T_{ISCK_REV}	REV pin setup with respect to CLK	1.23	1.23	ns
T_{ISCK_SR}	SR pin setup with respect to CLKDIV	0.77	0.92	ns
Setup/Hold for Data Lines				
$T_{ISDCK_D} / T_{ISCKD_D}$	D pin setup/hold with respect to CLK (IOBDELAY = IBUF or NONE)	0.28/-0.11	0.34/-0.11	ns
	D pin setup/hold with respect to CLK (IOBDELAY = IFD or BOTH, IOBDELAY_TYPE = DEFAULT)	7.63/-6.51	8.84/-6.51	ns
	D pin setup/hold with respect to CLK ⁽¹⁾ (IOBDELAY = IFD or BOTH, IOBDELAY_TYPE = FIXED, IOBDELAY_VALUE = 0)	0.87/-0.68	1.08/-0.68	ns
$T_{ISDCK_DDR} / T_{ISCKD_DDR}$	D pin setup/hold with respect to CLK at DDR mode (IOBDELAY = IBUF or NONE)	0.28/-0.11	0.34/-0.11	ns
	D pin setup/hold with respect to CLK at DDR mode (IOBDELAY = IFD or BOTH, IOBDELAY_TYPE = DEFAULT)	7.63/-6.51	8.84/-6.51	ns
	D pin setup/hold with respect to CLK at DDR mode ⁽¹⁾ (IOBDELAY = IFD or BOTH, IOBDELAY_TYPE = FIXED, IOBDELAY_VALUE = 0)	0.87/-0.68	1.08/-0.68	ns
Sequential Delays				
T_{ISCKO_Q}	CLKDIV to out at Q pin	0.71	0.85	ns
Propagation Delays				
$T_{ISDO_DO_IOBDELAY_IFD}$	D input to DO output pin (IOBDELAY = IFD)	0.20	0.24	ns
$T_{ISDO_DO_IOBDELAY_NONE}$	D input to DO output pin (IOBDELAY = NONE)	0.20	0.24	ns
$T_{ISDO_DO_IOBDELAY_BOTH}$	D input to DO output pin (IOBDELAY = BOTH, IOBDELAY_TYPE = DEFAULT)	6.91	7.96	ns
	D input to DO output pin ⁽¹⁾ (IOBDELAY = BOTH, IOBDELAY_TYPE = FIXED, IOBDELAY_VALUE = 0)	0.79	0.99	ns
$T_{ISDO_DO_IOBDELAY_IBUF}$	D input to DO output pin (IOBDELAY = IBUF, IOBDELAY_TYPE = DEFAULT)	6.91	7.96	ns
	D input to DO output pin ⁽¹⁾ (IOBDELAY = IBUF, IOBDELAY_TYPE = FIXED, IOBDELAY_VALUE = 0)	0.79	0.99	ns

Notes:

- Recorded at 0 tap value.
- T_{ISCK_CE2} and T_{ISCKC_CE2} are reported as $T_{ISCK_CE} / T_{ISCKC_CE}$ in TRCE report.

Input Delay Switching Characteristics

Table 30: Input Delay Switching Characteristics

Symbol	Description	Speed Grade		Units
		-11	-10	
T _{IDELAYRESOLUTION}	IDELAY Chain Delay Resolution	75	75	ps
T _{IDELAYTOTAL_ERR}	Cumulative delay at a given tap ⁽³⁾	[(tap - 1) x 75 + 34] ± 0.07[(tap - 1) x 75 + 34]		ps
T _{IDELAYCTRLCO_RDY}	Reset to Ready for IDELAYCTRL (Maximum)	3.00	3.00	µs
F _{IDELAYCTRL_REF}	REFCLK frequency	200	200	MHz
IDELAYCTRL_REF_PRECISION ⁽²⁾	REFCLK precision	±10	±10	MHz
T _{IDELAYCTRL_RPW}	Minimum Reset pulse width	50.0	50.0	ns
T _{IDELAYPAT_JIT}	Pattern dependent period jitter in delay chain for clock pattern	0	0	Note 1
	Pattern dependent period jitter in delay chain for random data pattern (PRBS 23)	10 ± 2	10 ± 2	Note 1

Notes:

1. Units in ps peak-to-peak per tap.
2. See the “REFCLK - Reference Clock” section (specific to IDELAYCTRL) in the *Virtex-4 FPGA User Guide*, Chapter 7, SelectIO Logic Resources.
3. This value accounts for tap 0, an anomaly in the tap chain with an average value of 34 ps.

Output Serializer/Deserializer Switching Characteristics

Table 31: OSERDES Switching Characteristics

Symbol	Description	Speed Grade		Units
		-11	-10	
Setup/Hold				
T _{OSDCK_D} /T _{OSCKD_D}	D input setup/hold with respect to CLKDIV	0.42/-0.04	0.50/-0.03	ns
T _{OSDCK_T} /T _{OSCKD_T} ⁽¹⁾	T input setup/hold with respect to CLK	0.52/-0.16	0.62/-0.16	ns
T _{OSDCK_T2} /T _{OSCKD_T2} ⁽¹⁾	T input setup/hold with respect to CLKDIV	0.42/-0.04	0.50/-0.03	ns
T _{OSCK_OCE} /T _{OSCKC_OCE}	OCE input setup/hold with respect to CLK	0.53/0.02	0.64/0.03	ns
T _{OSCK_S}	SR (Reset) input setup with respect to CLKDIV	0.80	0.96	ns
T _{OSCK_TCE} /T _{OSCKC_TCE}	TCE input setup/hold with respect to CLK	0.53/0.02	0.64/0.03	ns
Sequential Delays				
T _{OSCKO_OQ}	Clock to out from CLK to OQ	0.49	0.59	ns
T _{OSCKO_TQ}	Clock to out from CLK to TQ	0.49	0.59	ns
Combinatorial				
T _{OSDO_TTQ}	T input to TQ Out	0.65	0.76	ns
T _{OSCO_OQ}	Asynchronous Reset to OQ	1.37	1.64	ns
T _{OSCO_TQ}	Asynchronous Reset to TQ	1.37	1.64	ns

Notes:

1. T_{OSDCK_T2} and T_{OSCKD_T2} are reported as T_{OSDCK_T}/T_{OSCKD_T} in TRCE report.

CLB Switching Characteristics

Table 32: CLB Switching Characteristics

Symbol	Description	Speed Grade		Units
		-11	-10	
Combinatorial Delays				
T_{ILO}	4-input function: F/G inputs to X/Y outputs	0.17	0.20	ns, max
T_{IF5}	5-input function: F/G inputs to F5 output	0.40	0.46	ns, max
T_{IF5X}	5-input function: F/G inputs to X output	0.49	0.57	ns, max
T_{IF6Y}	FXINA or FXINB inputs to YMUX output	0.34	0.39	ns, max
T_{INAFX}	FXINA input to FX output via MUXFX	0.23	0.27	ns, max
T_{INBFX}	FXINB input to FX output via MUXFX	0.23	0.26	ns, max
T_{BXX}	BX input to XMUX output	0.65	0.76	ns, max
T_{BYY}	BY input to YMUX output	0.48	0.56	ns, max
T_{BXCY}	BX input to C_{OUT} output – Getting into carry chain ⁽²⁾	0.66	0.78	ns, max
T_{BYCY}	BY input to C_{OUT} output – Getting into carry chain ⁽²⁾	0.54	0.63	ns, max
T_{BYP}	C_{IN} input to C_{OUT} output – Carry chain delay ⁽²⁾	0.08	0.09	ns, max
T_{OPCYF}	F input to C_{OUT} output – Getting out from carry chain ⁽²⁾	0.50	0.58	ns, max
T_{OPCYG}	G input to C_{OUT} output – Getting out from carry chain ⁽²⁾	0.48	0.57	ns, max
Sequential Delays				
T_{CKO}	FF Clock CLK to XQ/YQ outputs	0.31	0.36	ns, max
T_{CKLO}	Latch Clock CLK to XQ/YQ outputs	0.41	0.48	ns, max
Setup-and-Hold Times of CLB Flip-Flops Before/After Clock CLK				
T_{DICK}/T_{CKDI}	BX/BY inputs	0.40/–0.09	0.47/–0.09	ns, min
T_{CECK}/T_{CKCE}	CE input	0.64/–0.16	0.75/–0.16	ns, min
T_{FXCK}/T_{CKFX}	FXINA/FXINB inputs	0.46/–0.14	0.54/–0.14	ns, min
T_{SRCK}/T_{CKSR}	SR/BY inputs (synchronous)	1.15/–0.73	1.35/–0.73	ns, min
T_{CINCK}/T_{CKCIN}	C_{IN} Data Inputs (DI) – Getting out from carry chain ⁽²⁾	0.57/–0.23	0.67/–0.23	ns, min
Set/Reset				
T_{RPW}	Minimum Pulse Width, SR/BY inputs	0.59	0.70	ns, min
T_{RQ}	Delay from SR/BY inputs to XQ/YQ outputs (asynchronous)	1.15	1.35	ns, max
F_{TOG}	Toggle Frequency (MHz) (for export control)	1205 ⁽³⁾	1028	MHz

Notes:

1. A zero “0” hold time listing indicates no hold time or a negative hold time. Negative values can not be guaranteed “best-case,” but if a “0” is listed, there is no positive hold time.
2. These items are of interest for carry chain applications.
3. XQ4VFX -11 devices are 1181 MHz.

CLB Distributed RAM Switching Characteristics (SLICEM Only)

Table 33: CLB Distributed RAM Switching Characteristics

Symbol	Description	Speed Grade		Units
		-11	-10	
Sequential Delays				
T _{SHCKO}	Clock CLK to X outputs (WE active)	1.77	2.08	ns, max
T _{SHCKOF5}	Clock CLK to F5 output (WE active)	1.69	1.98	ns, max
Setup-and-Hold Times Before/After Clock CLK				
T _{DS} /T _{DH}	BX/BY data inputs (DI)	1.46/-0.88	1.80/-0.88	ns, min
T _{AS} /T _{AH}	F/G address inputs	0.97/-0.34	1.13/-0.29	ns, min
T _{WS} /T _{WH}	WE input (SR)	1.21/-0.47	1.42/-0.47	ns, min
Clock CLK				
T _{WPH}	Minimum Pulse Width, High	0.59	0.69	ns, min
T _{WPL}	Minimum Pulse Width, Low	0.60	0.70	ns, min
T _{WC}	Minimum clock period to meet address write cycle time	0.84	0.98	ns, min

Notes:

1. A zero "0" hold time listing indicates no hold time or a negative hold time. Negative values cannot be guaranteed "best-case," but if a "0" is listed, there is no positive hold time.
2. T_{SHCKO} also represents the CLK to XMUX output. Refer to TRCE report for the CLK to XMUX path.

CLB Shift Register Switching Characteristics (SLICEM Only)

Table 34: CLB Shift Register Switching Characteristics

Symbol	Description	Speed Grade			Units
		-11		-10	
		XQ4VFX	XQ4VLX/SX	All	
Sequential Delays					
T _{REG}	Clock CLK to X/Y outputs	2.19	2.19	2.57	ns, max
T _{REGXB}	Clock CLK to XB output via MC15 LUT output	1.90	1.84	2.04	ns, max
T _{REGYB}	Clock CLK to YB output via MC15 LUT output	1.92	1.85	2.17	ns, max
T _{CKSH}	Clock CLK to Shiftout	1.76	1.70	1.99	ns, max
T _{REGF5}	Clock CLK to F5 output	2.11	2.11	2.47	ns, max
Setup-and-Hold Times Before/After Clock CLK					
T _{WS} /T _{WH}	WE input (SR)	0.96/-0.70	0.96/-0.70	1.12/-0.62	ns, min
T _{DS} /T _{DH}	BX/BY data inputs (DI)	1.45/-1.11	1.45/-1.11	1.75/-1.11	ns, min
Clock CLK					
T _{WPH}	Minimum Pulse Width, High	0.59	0.59	0.69	ns, min
T _{WPL}	Minimum Pulse Width, Low	0.60	0.60	0.70	ns, min

Notes:

1. A zero "0" hold time listing indicates no hold time or a negative hold time. Negative values cannot be guaranteed "best-case," but if a "0" is listed, there is no positive hold time.

Block RAM and FIFO Switching Characteristics

Table 35: Block RAM Switching Characteristics

Symbol	Description	Speed Grade		Units
		-11	-10	
Sequential Delays				
T _{RCKO_DORA}	Clock CLK to DOUT output (without output register) ⁽²⁾	1.83	2.10	ns, max
T _{RCKO_DOA}	Clock CLK to DOUT output (with output register) ⁽³⁾	0.80	0.92	ns, min
Setup-and-Hold Times Before Clock CLK				
T _{RCKK_ADDR} /T _{RCKC_ADDR}	ADDR inputs	0.37/0.28	0.43/0.33	ns, min
T _{RDCK_DI} /T _{RCKD_DI}	DIN inputs ⁽⁴⁾	0.20/0.28	0.23/0.33	ns, min
T _{RCKK_EN} /T _{RCKC_EN}	EN input ⁽⁵⁾	0.45/0.28	0.52/0.33	ns, min
T _{RCKK_REGCE} /T _{RCKC_REGCE}	CE input of output register	0.27/0.28	0.32/0.33	ns, min
T _{RCKK_SSR} /T _{RCKC_SSR}	RST input	0.27/0.28	0.32/0.33	ns, min
T _{RCKK_WE} /T _{RCKC_WE}	WEN input	0.65/0.28	0.75/0.33	ns, min
Maximum Frequency				
F _{MAX}	Write first and no change mode	450.45	400.00	MHz
F _{MAX}	Read first mode	450.45	400.00	MHz

Notes:

1. A zero "0" hold time listing indicates no hold time or a negative hold time. Negative values can not be guaranteed "best-case," but if a "0" is listed, there is no positive hold time.
2. T_{RCKO_DORA} includes T_{RCKO_DOWA}, T_{RCKO_DOPAR}, and T_{RCKO_DOPAW} as well as the B port equivalent timing parameters.
3. T_{RCKO_DOA} includes T_{RCKO_DOPA} as well as the B port equivalent timing parameters.
4. T_{RCKO_DI} includes both A and B inputs as well as the parity inputs of A and B.
5. Xilinx Block RAMs do not have asynchronous inputs on an enabled port address. During the time that a port is enabled, its addresses must be stable during the specified set-up time. Do not create an asynchronous input on an enabled port address.

Table 36: FIFO Switching Characteristics

Symbol	Description	Speed Grade		Units
		-11	-10	
Sequential Delays				
T _{FCKO_DO}	Clock CLK to DO output ⁽²⁾	0.80	0.92	ns, max
T _{FCKO_FLAGS}	Clock CLK to FIFO flags outputs ⁽³⁾	1.04	1.19	ns, max
T _{FCKO_POINTERS}	Clock CLK to FIFO pointer outputs ⁽⁴⁾	1.29	1.48	ns, max
Setup-and-Hold Times Before Clock CLK				
T _{FDCK_DI} /T _{FCKD_DI}	DI input ⁽⁵⁾	0.20/0.28	0.23/0.33	ns, min
T _{FCCK_EN} /T _{FCKC_EN}	Enable inputs ⁽⁶⁾	0.73/0.28	0.84/0.33	ns, min
Reset Delays				
T _{FCO_FLAGS}	Reset RST to FLAGS ⁽⁷⁾	1.46	1.68	ns, max
Maximum Frequency				
F _{MAX}	FIFO in all modes	450.45	400.00	MHz

Notes:

1. A zero "0" hold time listing indicates no hold time or a negative hold time. Negative values can not be guaranteed "best-case," but if a "0" is listed, there is no positive hold time.
2. T_{FCKO_DO} includes parity output (T_{FCKO_DOP}).
3. T_{FCKO_FLAGS} includes the following parameters: T_{FCKO_AEMPTY}, T_{FCKO_AFULL}, T_{FCKO_EMPTY}, T_{FCKO_FULL}, T_{FCKO_RDERR}, T_{FCKO_WRERR}.
4. T_{FCKO_POINTERS} includes both T_{FCKO_RDCOUNT} and T_{FCKO_WRCOUNT}.
5. T_{FDCK_DI} includes parity inputs (T_{FDCK_DIP}).
6. T_{FCCK_EN} includes both WRITE and READ enable.
7. T_{FCO_FLAGS} includes the following flags: AEMPTY, AFULL, EMPTY, FULL, RDERR, WRERR, RDCOUNT and WRCOUNT.

XtremeDSP Switching Characteristics

Table 37: XtremeDSP™ Switching Characteristics

Symbol	Description	Speed Grade		Units
		-11	-10	
Setup and Hold of CE Pins				
$T_{DSPCK_CE}/T_{DSPCK_CE}$	Setup/hold of all CE inputs of the DSP48 slice	0.43/0.10	0.49/0.12	ns
$T_{DSPCK_RST}/T_{DSPCK_RST}$	Setup/hold of all RST inputs of the DSP48 slice	0.36/0.10	0.40/0.12	ns
Setup-and-Hold Times of Data				
$T_{DSPDCK_AA, BB, CC}/T_{DSPCKD_AA, BB, CC}$	Setup/hold of {A, B, C} input to {A, B, C} register	0.28/0.26	0.32/0.29	ns
$T_{DSPDCK_AM, BM}/T_{DSPCKD_AM, BM}$	Setup/hold of {A, B} input to M register	2.03/0.00	2.28/0.00	ns
Sequential Delays				
T_{DSPCKO_PP}	Clock to out from P register to P output	0.71	0.79	ns
T_{DSPCKO_PM}	Clock to out from M register to P output	2.65	2.98	ns
Combinatorial				
$T_{DSPDO_AP, BP}L$	From {A, B} input to P output (LEGACY_MODE = MULT18X18)	3.92	4.41	ns
Maximum Frequency				
F_{MAX}	From {A, B} register to P register (LEGACY_MODE = MULT18X18)	285.71	253.94	MHz
	Fully Pipelined	450.05	400.00	MHz

Configuration Switching Characteristics

Table 38: Configuration Switching Characteristics

Symbol	Description	Speed Grade			Units
		-11	-10		
		I-Grade	I-Grade	M-Grade	
Power-up Timing Characteristics					
T_{PL}	Program latency	0.5	0.5	0.5	μs/frame, max
T_{POR}	Power-on-reset	$T_{PL} + 10$			ms, max
T_{ICCK}	CCLK (output) delay	500	500	500	ns, min
$T_{PROGRAM}$	Program Pulse Width	300	300	400	ns, min
Master/Slave Serial Mode Programming Switching					
T_{DCC}/T_{CCD}	DIN setup/hold, slave mode	0.5/1.0	0.5/1.0	1.0/1.0	ns, min
T_{DSCK}/T_{SCKD}	DIN setup/hold, master mode	0.5/1.0	0.5/1.0	1.0/1.0	ns, min
T_{CCO}	DOUT	7.5	7.5	8.0	ns, max
T_{CCH}	High time	2.0	2.0	2.0	ns, min
T_{CCL}	Low time	2.0	2.0	2.0	ns, min
F_{CC_SERIAL}	Maximum frequency, master mode with respect to nominal CCLK.	100	100	80	MHz, max
F_{MCCTOL}	Frequency tolerance, master mode with respect to nominal CCLK.	±50	±50	±50	%
F_{MAX_SLAVE}	Slave mode external CCLK	100	100	80	MHz

Table 38: Configuration Switching Characteristics (Cont'd)

Symbol	Description	Speed Grade			Units
		-11	-10		
		I-Grade	I-Grade	M-Grade	
SelectMAP Mode Programming Switching					
T _{SMDCC} /T _{SMCCD}	SelectMAP setup/hold	2.0/0.0	2.0/0.0	3.0/0.0	ns, min
T _{SMCSCC} /T _{SMCCCS}	CS_B setup/hold	1.0/0.5	1.0/0.5	2.0/0.5	ns, min
T _{SMCCW} /T _{SMWCC}	RDWR_B setup/hold	6.0/1.0	6.0/1.0	8.0/1.0	ns, min
T _{SMCKBY}	BUSY propagation delay	8.0	8.0	8.0	ns, max
F _{CC_SELECTMAP}	Maximum frequency, master mode with respect to nominal CCLK.	100	100	80	MHz, max
F _{MCCTOL}	Frequency tolerance, master mode with respect to nominal CCLK.	±50	±50	±50	%
Boundary-Scan Port Timing Specifications					
T _{TAPTCK}	TMS and TDI setup time before TCK	1.0	1.0	1.5	ns, min
T _{TCKTAP}	TMS and TDI hold time after TCK	2.0	2.0	2.0	ns, min
T _{TCKTDO}	TCK falling edge to TDO output valid	6.0	6.0	8.0	ns, max
F _{TCK}	Maximum configuration TCK clock frequency	66	66	66	MHz, max
F _{TCKB}	Maximum Boundary-Scan TCK clock frequency	50	50	50	MHz, max
Dynamic Reconfiguration Port (DRP) for DCM					
CLKIN_FREQ_DLL_HF_MS_MAX	Maximum frequency for DCLK	450	400	400	MHz, max
D_DCMADV_DADDR_DCLK_SETUP/ D_DCMADV_DADDR_DCLK_HOLD	DADDR setup/hold	0.63/0.00	0.72/0.00	0.72/0.00	ns, max
D_DCMADV_DI_DCLK_SETUP/ D_DCMADV_DI_DCLK_HOLD	DI setup/hold	0.63/0.00	0.72/0.00	0.72/0.00	ns, max
D_DCMADV_DEN_DCLK_SETUP/ D_DCMADV_DEN_DCLK_HOLD	DEN setup/hold time	0.58/0.00	0.58/0.00	0.58/0.00	ns, max
D_DCMADV_DWE_DCLK_SETUP/ D_DCMADV_DWE_DCLK_HOLD	DWE setup/hold time	0.58/0.00	0.58/0.00	0.58/0.00	ns, max
D_DCMADV_DCLK_DO	CLK to out of DO ⁽¹⁾	0	0	0	ns, max
D_DCMADV_DCLK_DRDY	CLK to out of DRDY	0.80	0.92	0.92	ns, max

Notes:

- DO holds until next DRP operation.

Master/Slave SelectMAP Parameters

Figure 3 is a generic timing diagram for data loading using SelectMAP. For other data loading diagrams, refer to the Virtex-4 FPGA User Guide.

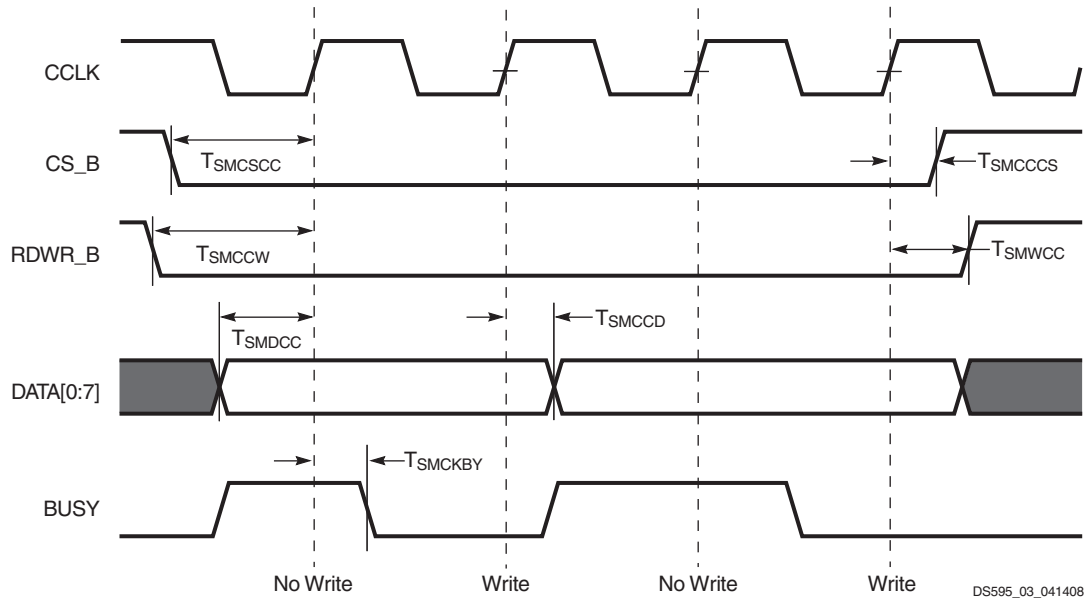


Figure 3: SelectMAP Mode Data Loading Sequence (Generic)

Clock Buffers and Networks

Table 39: Global Clock Switching Characteristics (Including BUFCTRL)

Symbol	Description	Speed Grade		Units
		-11	-10	
$T_{BCCCK_CE}/T_{BCCCK_CE}^{(1)}$	CE pins setup/hold	0.31/0.00	0.35/0.00	ns
$T_{BCCCK_S}/T_{BCCCK_S}^{(1)}$	S pins setup/hold	0.31/0.00	0.35/0.00	ns
T_{BCCCKO_O}	BUFCTRL delay	0.77	0.90	ns
Maximum Frequency				
F_{MAX}	Global clock tree	450	400	MHz

Notes:

- T_{BCCCK_CE} and T_{BCCCK_S} must be satisfied to assure glitch-free operation of the global clock when switching between clocks. These parameters do not apply to the BUFMUX_VIRTEX4 primitive that assures glitch-free operation. The other global clock setup-and-hold times are optional; only needing to be satisfied if device operation requires simulation matches on a cycle-for-cycle basis when switching between clocks.

DCM and PMCD Switching Characteristics

DCM in Maximum Range (MR) Mode is not supported for M-grade devices.

Table 40: Operating Frequency Ranges for DCM in Maximum Speed (MS) Mode

Symbol	Description	Speed Grade		Units
		-11	-10	
Outputs Clocks (Low Frequency Mode)				
CLKOUT_FREQ_1X_LF_MS_MIN	CLK0, CLK90, CLK180, CLK270	32	32	MHz
CLKOUT_FREQ_1X_LF_MS_MAX		150	150	MHz
CLKOUT_FREQ_2X_LF_MS_MIN	CLK2X, CLK2X180	64	64	MHz
CLKOUT_FREQ_2X_LF_MS_MAX		300	300	MHz
CLKOUT_FREQ_DV_LF_MS_MIN	CLKDV	2	2	MHz
CLKOUT_FREQ_DV_LF_MS_MAX		100	100	MHz

Table 40: Operating Frequency Ranges for DCM in Maximum Speed (MS) Mode (Cont'd)

Symbol	Description	Speed Grade		Units
		-11	-10	
CLKOUT_FREQ_FX_LF_MS_MIN	CLKFX, CLKFX180	32	32	MHz
CLKOUT_FREQ_FX_LF_MS_MAX		210	210	MHz
Input Clocks (Low Frequency Mode)				
CLKIN_FREQ_DLL_LF_MS_MIN	CLKIN (using DLL outputs) ⁽¹⁾⁽³⁾⁽⁴⁾⁽⁵⁾	32	32	MHz
CLKIN_FREQ_DLL_LF_MS_MAX		150	150	MHz
CLKIN_FREQ_FX_LF_MS_MIN	CLKIN (using DFS outputs only) ⁽²⁾⁽³⁾⁽⁴⁾	1	1	MHz
CLKIN_FREQ_FX_LF_MS_MAX		210	210	MHz
PSCLK_FREQ_LF_MS_MIN	PSCLK	1	1	KHz
PSCLK_FREQ_LF_MS_MAX		450	400	MHz
Outputs Clocks (High Frequency Mode)				
CLKOUT_FREQ_1X_HF_MS_MIN	CLK0, CLK90, CLK180, CLK270	150	150	MHz
CLKOUT_FREQ_1X_HF_MS_MAX		450	400	MHz
CLKOUT_FREQ_2X_HF_MS_MIN	CLK2X, CLK2X180	300	300	MHz
CLKOUT_FREQ_2X_HF_MS_MAX		450	400	MHz
CLKOUT_FREQ_DV_HF_MS_MIN	CLKDV	9.4	9.4	MHz
CLKOUT_FREQ_DV_HF_MS_MAX		300	267	MHz
CLKOUT_FREQ_FX_HF_MS_MIN	CLKFX, CLKFX180	210	210	MHz
CLKOUT_FREQ_FX_HF_MS_MAX		315	300	MHz
Input Clocks (High Frequency Mode)				
CLKIN_FREQ_DLL_HF_MS_MIN	CLKIN (using DLL outputs) ⁽¹⁾⁽³⁾⁽⁴⁾	150	150	MHz
CLKIN_FREQ_DLL_HF_MS_MAX		450	400	MHz
CLKIN_FREQ_FX_HF_MS_MIN	CLKIN (using DFS outputs only) ⁽²⁾⁽³⁾⁽⁴⁾	50	50	MHz
CLKIN_FREQ_FX_HF_MS_MAX		315	300	MHz
PSCLK_FREQ_HF_MS_MIN	PSCLK	1	1	KHz
PSCLK_FREQ_HF_MS_MAX		450	400	MHz

Notes:

1. DLL outputs are used in these instances to describe the outputs: CLK0, CLK90, CLK180, CLK270, CLK2X, CLK2X180, and CLKDV.
2. DFS outputs are used in these instances to describe the outputs: CLKFX and CLKFX180.
3. When using the DCMs CLKIN_DIVIDE_BY_2 attribute these values should be doubled.
4. When using a CLKIN frequency > 400 MHz and the DCMs CLKIN_DIVIDE_BY_2 attribute, the CLKIN duty cycle must be within ±5% (45/55 to 55/45).
5. The DCM must be reset if the clock input clock stops for more than 100 ms.

Table 41: Operating Frequency Ranges for DCM in Maximum Range (MR) Mode (Industrial Grade Only)⁽⁵⁾

Symbol	Description	Speed Grade		Units
		-11	-10	
Outputs Clocks (Low Frequency Mode)				
CLKOUT_FREQ_1X_LF_MR_MIN	CLK0, CLK90, CLK180, CLK270	19	19	MHz
CLKOUT_FREQ_1X_LF_MR_MAX		36	32	MHz
CLKOUT_FREQ_2X_LF_MR_MIN	CLK2X, CLK2X180	38	38	MHz
CLKOUT_FREQ_2X_LF_MR_MAX		72	64	MHz
CLKOUT_FREQ_DV_LF_MR_MIN	CLKDV	1.2	1.2	MHz
CLKOUT_FREQ_DV_LF_MR_MAX		24	21.3	MHz
CLKOUT_FREQ_FX_LF_MR_MIN	CLKFX, CLKFX180	19	19	MHz
CLKOUT_FREQ_FX_LF_MR_MAX		36	32	MHz
Input Clocks (Low Frequency Mode)				
CLKIN_FREQ_DLL_LF_MR_MIN	CLKIN (using DLL outputs) ⁽¹⁾⁽³⁾⁽⁴⁾	19	19	MHz
CLKIN_FREQ_DLL_LF_MR_MAX		36	32	MHz
CLKIN_FREQ_FX_LF_MR_MIN	CLKIN (using DFS outputs only) ⁽²⁾⁽³⁾⁽⁴⁾	1	1	MHz
CLKIN_FREQ_FX_LF_MR_MAX		32	28	MHz
PSCLK_FREQ_LF_MR_MIN	PSCLK	1	1	KHz
PSCLK_FREQ_LF_MR_MAX		236.30	210.00	MHz

Notes:

1. DLL Outputs are used in these instances to describe the outputs: CLK0, CLK90, CLK180, CLK270, CLK2X, CLK2X180, and CLKDV.
2. DFS Outputs are used in these instances to describe the outputs: CLKFX and CLKFX180.
3. When using the DCMs CLKIN_DIVIDE_BY_2 attribute these values should be doubled.
4. When using a CLKIN frequency > 400 MHz and the DCMs CLKIN_DIVIDE_BY_2 attribute, the CLKIN duty cycle must be within ±5% (45/55 to 55/45).
5. DCM in Maximum Range (MR) Mode is not supported for M-grade devices.

Table 42: Input Clock Duty Cycle Input Tolerance

Symbol	Description	Frequency Range	Value	Units
CLKIN_PSCLK_PULSE_RANGE_1	PSCLK only	< 1 MHz	25 – 75	%
CLKIN_PSCLK_PULSE_RANGE_1_50	PSCLK and CLKIN	1 – 50 MHz	25 – 75	%
CLKIN_PSCLK_PULSE_RANGE_50_100		50 – 100 MHz	30 – 70	%
CLKIN_PSCLK_PULSE_RANGE_100_200		100 – 200 MHz	40 – 60	%
CLKIN_PSCLK_PULSE_RANGE_200_400		200 – 400 MHz	45 – 55	%

Table 43: Input Clock Tolerances

Symbol	Description	Speed Grade		Units
		-11	-10	
Input Clock Cycle-Cycle Jitter (Low Frequency Mode)				
CLKIN_CYC_JITT_DLL_LF	CLKIN (using DLL outputs) ⁽¹⁾	±300	±300	ps
CLKIN_CYC_JITT_FX_LF	CLKIN (using DFS outputs) ⁽²⁾	±300	±300	ps
Input Clock Cycle-Cycle Jitter (High Frequency Mode)				
CLKIN_CYC_JITT_DLL_HF	CLKIN (using DLL outputs) ⁽¹⁾	±150	±150	ps
CLKIN_CYC_JITT_FX_HF	CLKIN (using DFS outputs) ⁽²⁾	±150	±150	ps
Input Clock Period Jitter (Low Frequency Mode)				
CLKIN_PER_JITT_DLL_LF	CLKIN (using DLL outputs) ⁽¹⁾	±1.0	±1.0	ns

Table 43: Input Clock Tolerances (Cont'd)

Symbol	Description	Speed Grade		Units
		-11	-10	
CLKIN_PER_JITT_FX_LF	CLKIN (using DFS outputs) ⁽²⁾	±1.0	±1.0	ns
Input Clock Period Jitter (High Frequency Mode)				
CLKIN_PER_JITT_DLL_HF	CLKIN (using DLL outputs) ⁽¹⁾	±1.0	±1.0	ns
CLKIN_PER_JITT_FX_HF	CLKIN (using DFS outputs) ⁽²⁾	±1.0	±1.0	ns
Feedback Clock Path Delay Variation				
CLKFB_DELAY_VAR_EXT	CLKFB off-chip feedback	±1.0	±1.0	ns

Notes:

1. DLL Outputs are used in these instances to describe the outputs: CLK0, CLK90, CLK180, CLK270, CLK2X, CLK2X180, and CLKDV.
2. DFS Outputs are used in these instances to describe the outputs: CLKFX and CLKFX180.
3. If both DLL and DFS outputs are used, follow the more restrictive specifications.

Output Clock Jitter

Table 44: Output Clock Jitter

Symbol	Description	Speed Grade		Units
		-11	-10	
Clock Synthesis Period Jitter				
CLK0	CLKOUT_PER_JITT_0	±100	±100	ps
CLK90	CLKOUT_PER_JITT_90	±150	±150	ps
CLK180	CLKOUT_PER_JITT_180	±150	±150	ps
CLK270	CLKOUT_PER_JITT_270	±150	±150	ps
CLK2X, CLK2X180	CLKOUT_PER_JITT_2X	±200	±200	ps
CLKDV (integer division)	CLKOUT_PER_JITT_DV1	±150	±150	ps
CLKDV (non-integer division)	CLKOUT_PER_JITT_DV2	±300	±300	ps
CLKFX, CLKFX180	CLKOUT_PER_JITT_FX	Note 1	Note 1	ps

Notes:

1. Values for this parameter are available at www.xilinx.com.

Output Clock Phase Alignment

Table 45: Output Clock Phase Alignment

Description	Symbol	Speed Grade			Units
		-11	-10		
		I-Grade	I-Grade	M-Grade	
Phase Offset Between CLKIN and CLKFB					
CLKIN/CLKFB	CLKIN_CLKFB_PHASE	±120	±120	±120	ps
Phase Offset Between Any DCM Outputs					
All CLK outputs	CLKOUT_PHASE	±140	±140	±200	ps
Duty Cycle Precision					
DLL outputs ⁽¹⁾	CLKOUT_DUTY_CYCLE_DLL ⁽³⁾⁽⁴⁾	±150	±150	±150	ps
DFS outputs ⁽²⁾	CLKOUT_DUTY_CYCLE_FX ⁽⁴⁾	±200	±200	±250	ps

Notes:

1. DLL Outputs are used in these instances to describe the outputs: CLK0, CLK90, CLK180, CLK270, CLK2X, CLK2X180, and CLKDV.
2. DFS Outputs are used in these instances to describe the outputs: CLKFX and CLKFX180.
3. CLKOUT_DUTY_CYCLE_DLL applies to the 1X clock outputs (CLK0, CLK90, CLK180, and CLK270) only if DUTY_CYCLE_CORRECTION=TRUE.
4. The measured value includes the duty cycle distortion of the global clock tree.

Table 46: Miscellaneous Timing Parameters

Symbol	Description	Speed Grade		Units
		-11	-10	
Time Required to Achieve LOCK				
T_LOCK_DLL_240	DLL output – Frequency range > 240 MHz ⁽¹⁾	20	20	µs
T_LOCK_DLL_120_240	DLL output – Frequency range 120 – 240 MHz ⁽¹⁾	63	63	µs
T_LOCK_DLL_60_120	DLL output – Frequency range 60 – 120 MHz ⁽¹⁾	225	225	µs
T_LOCK_DLL_50_60	DLL output – Frequency range 50 – 60 MHz ⁽¹⁾	325	325	µs
T_LOCK_DLL_40_50	DLL output – Frequency range 40 – 50 MHz ⁽¹⁾	500	500	µs
T_LOCK_DLL_30_40	DLL output – Frequency range 30 – 40 MHz ⁽¹⁾	900	900	µs
T_LOCK_DLL_24_30	DLL output – Frequency range 24 – 30 MHz ⁽¹⁾	1250	1250	µs
T_LOCK_DLL_30	DLL output – Frequency range < 30 MHz ⁽¹⁾	1250	1250	µs
T_LOCK_FX_MIN	DFS outputs ⁽²⁾	10	10	ms
T_LOCK_FX_MAX		10	10	ms
T_LOCK_DLL_FINE_SHIFT	Multiplication factor for DLL lock time with Fine Shift	2	2	–
Fine Phase Shifting				
FINE_SHIFT_RANGE_MS	Absolute shifting range in maximum speed mode	7	7	ns
FINE_SHIFT_RANGE_MR ⁽⁷⁾	Absolute shifting range in maximum range mode	10	10	ns
Delay Lines				
DCM_TAP_MS_MIN	Tap delay resolution (Min) in maximum speed mode	5	5	ps
DCM_TAP_MS_MAX	Tap delay resolution (Max) in maximum speed mode	40	40	ps
DCM_TAP_MR_MIN ⁽⁷⁾	Tap delay resolution (Min) in maximum range mode	10	10	ps
DCM_TAP_MR_MAX ⁽⁷⁾	Tap delay resolution (Max) in maximum range mode	60	60	ps
DCM_RESET ⁽³⁾	Minimum duration that RST must be held asserted	200	200	ms
	Maximum duration that RST can be held asserted ⁽⁴⁾	10	10	sec

Table 46: Miscellaneous Timing Parameters (Cont'd)

Symbol	Description	Speed Grade		Units
		-11	-10	
DCM_INPUT_CLOCK_STOP	Maximum duration that CLKIN and CLKFB can be stopped ⁽⁵⁾⁽⁶⁾	100	100	ms

Notes:

1. DLL Outputs are used in these instances to describe the outputs: CLK0, CLK90, CLK180, CLK270, CLK2X, CLK2X180, and CLKDV.
2. DFS Outputs are used in these instances to describe the outputs: CLKFX and CLKFX180.
3. CLKIN must be present and stable during the DCM_RESET.
4. This only applies to production step 1 LX and SX devices. For these devices, use the design solutions described in answer record 21127 for support of longer reset durations. Production step 2 LX and SX devices and all production FX devices do not have this requirement.
5. For production step 1 LX and SX devices, use the design solutions described in answer record 21127 for support of longer durations of stopped clocks. For production step 2 LX and SX devices and all production FX devices, the ISE software automatically inserts a small macro to support longer durations of stopped clocks.
6. For all stepping levels, once the input clock is toggling again and stable after being stopped, DCM must be reset.
7. DCM in Maximum Range (MR) Mode is not supported for M-grade devices.

Table 47: Frequency Synthesis

Attribute	Min	Max
CLKFX_MULTIPLY	2	32
CLKFX_DIVIDE	1	32

Table 48: DCM Switching Characteristics

Symbol	Description	Speed Grade		Units
		-11	-10	
$T_{DMCCK_PSEN} / T_{DMCKC_PSEN}$	PSEN setup/hold	0.93/0.00	1.07/0.00	ns
$T_{DMCCK_PSINCDEC} / T_{DMCKC_PSINCDEC}$	PSINCDEC setup/hold	0.93/0.00	1.07/0.00	ns
T_{DMCKO_PSDONE}	Clock to out of PSDONE	0.60	0.69	ns

Table 49: PMCD Switching Characteristic

Symbol	Description	Speed Grade		Units
		-11	-10	
$T_{PMCCCK_REL} / T_{PMCKC_REL}$	REL setup/hold for all outputs	0.60/0.00	0.60/0.00	ns
$T_{PMCCO_CLK\{A1,B,C,D\}}$	RST assertion to clock output deassertion	4.00	4.50	ns
$T_{PMCCO_CLK\{A1,B,C,D\}}$	Max clock propagation delay of PMCD for all outputs	4.60	5.20	ns
PMCD_CLK_SKEW	Max phase between all outputs assuming all inputs	±150	±150	ps
CLKIN_FREQ_PMCD_CLKA_MAX	Max input/output frequency	450	400	MHz
CLKIN_PSCLK_PULSE_RANGE	Max duty-cycle input tolerance (same as DCM)	Note 1	Note 1	–
PMCD_REL_HIGH_PULSE_MIN	Min pulse width for REL	1.11	1.25	ns
PMCD_RST_HIGH_PULSE_MIN	Min pulse width for RST	1.11	1.25	ns

Notes:

1. Refer to Table 42, page 30 parameter: CLKIN_PSCLK_PULSE_RANGE.

System-Synchronous Switching Characteristics

Virtex-4Q Pin-to-Pin Output Parameter Guidelines

All devices are 100% functionally tested. The representative values for typical pin locations and normal clock loading are listed in Table 50. Values are expressed in nanoseconds unless otherwise noted.

Table 50: Global Clock Input-to-Output Delay for LVCMOS25, 12 mA, Fast Slew Rate, With DCM

Symbol	Description	Device	Speed Grade			Units
			-11	-10		
			I-Grade	I-Grade	M-Grade	
LVCMOS25 Global Clock Input-to-Output Delay using Output Flip-Flop, 12mA, Fast Slew Rate, with DCM.						
T _{ICKOFDCM}	Global Clock and OFF with DCM	XQ4VLX25	–	–	3.36	ns
		XQ4VLX40	–	3.32	3.42	ns
		XQ4VLX60	–	3.45	3.53	ns
		XQ4VLX80	3.27	–	–	ns
		XQ4VLX100	3.33	3.79	–	ns
		XQ4VLX160	–	3.82	–	ns
		XQ4VSX55	–	3.62	4.14	ns
		XQ4VFX60	–	3.77	3.96	ns
		XQ4VFX100	3.58	–	–	ns

Notes:

1. Listed above are representative values where one global clock input drives one vertical clock line in each accessible column, and where all accessible IOB and CLB flip-flops are clocked by the global clock net.
2. DCM output jitter is already included in the timing calculation.
3. Clock to out has +320 ps offset for operation outside of the industrial temperature range.

Table 51: Global Clock Input-to-Output Delay for LVCMOS25, 12 mA, Fast Slew Rate, Without DCM

Symbol	Description	Device	Speed Grade			Units
			-11	-10		
			I-Grade	I-Grade	M-Grade	
LVCMOS25 Global Clock Input-to-Output Delay using Output Flip-Flop, 12mA, Fast Slew Rate, without DCM.						
T _{ICKOF}	Global Clock and OFF without DCM	XQ4VLX25	–	–	8.34	ns
		XQ4VLX40	–	8.50	8.73	ns
		XQ4VLX60	–	8.70	8.94	ns
		XQ4VLX80	7.85	–	–	ns
		XQ4VLX100	8.15	9.18	–	ns
		XQ4VLX160	–	9.46	–	ns
		XQ4VSX55	–	9.00	9.54	ns
		XQ4VFX60	–	8.85	9.11	ns
		XQ4VFX100	8.40	–	–	ns

Notes:

1. Listed above are representative values where one global clock input drives one vertical clock line in each accessible column, and where all accessible IOB and CLB flip-flops are clocked by the global clock net.
2. Clock to out has +250 ps offset for operation outside of the industrial temperature range.

Virtex-4Q Pin-to-Pin Input Parameter Guidelines

All devices are 100% functionally tested. The representative values for typical pin locations and normal clock loading are listed in Table 52. Values are expressed in nanoseconds unless otherwise noted.

Table 52: Global Clock Setup and Hold for LVCMOS25 Standard, With DCM

Symbol	Description	Device	Speed Grade			Units
			-11	-10		
			I-Grade	I-Grade	M-Grade	
Input Setup-and-Hold Time Relative to Global Clock Input Signal for LVCMOS25 Standard.⁽¹⁾						
T _{PSDCM} /T _{PHDCM}	No Delay Global Clock and IFF with DCM ⁽²⁾	XQ4VLX25	–	–	1.65/–0.43	ns
		XQ4VLX40	–	1.50/–0.46	1.69/–0.46	ns
		XQ4VLX60	–	1.55/–0.36	1.71/–0.36	ns
		XQ4VLX80	1.42/–0.21	–	–	ns
		XQ4VLX100	1.48/–0.14	1.56/–0.08	–	ns
		XQ4VLX160	–	1.89/–0.05	–	ns
		XQ4VSX55	–	1.55/–0.13	1.73/–0.13	ns
		XQ4VFX60	–	1.44/0.09	1.53/0.12	ns
		XQ4VFX100	1.42/0.20	–	–	ns

Notes:

- Setup time is measured relative to the Global Clock input signal with the fastest route and the lightest load. Hold time is measured relative to the Global Clock input signal with the slowest route and heaviest load.
- These measurements include:
CLK0 DCM jitter
IFF = input flip-flop or latch
- Use IBIS to determine any duty-cycle distortion incurred using various standards.
- Hold time has +200 ps offset for operation outside of the industrial temperature range.

Table 53: Global Clock Setup and Hold for LVCMOS25 Standard, With DCM in Source-Synchronous Mode

Symbol	Description	Device	Speed Grade			Units
			-11	-10		
			I-Grade	I-Grade	M-Grade	
Example Data Input Setup-and-hold Times Relative to a Forwarded Clock Input Pin, Using DCM and Global Clock Buffer.(1)(3)						
T _{PSDCM_0} /T _{PHDCM_0}	No Delay Global Clock and IFF with DCM in Source-Synchronous Mode(2)	XQ4VLX25	–	–	–0.07/1.09	ns
		XQ4VLX40	–	–0.37/1.19	–0.03/1.19	ns
		XQ4VLX60	–	–0.32/1.29	–0.11/1.29	ns
		XQ4VLX80	–0.38/1.34	–	–	ns
		XQ4VLX100	–0.31/1.41	–0.31/1.57	–	ns
		XQ4VLX160	–	–0.31/1.89	–	ns
		XQ4VSX55	–	–0.32/1.52	–0.09/1.52	ns
		XQ4VFX60	–	–0.43/1.74	–0.25/1.77	ns
		XQ4VFX100	–0.38/1.75	–	–	ns

Notes:

1. The timing values were measured using the fine-phase adjustment feature of the DCM. These measurements include CLK0 DCM jitter. Package skew is not included in these measurements.
2. IFF = input flip-flop.
3. For situations where clock and data inputs conform to different standards, adjust the setup-and-hold values accordingly using the values shown in [IOB Switching Characteristics\(1\)\(2\), page 13](#).
4. Setup time has +150 ps offset for operation outside of the industrial temperature range.

Table 54: Global Clock Setup and Hold for LVCMOS25 Standard, Without DCM

Symbol	Description	Device	Speed Grade			Units
			-11	-10		
			I-Grade	I-Grade	M-Grade	
Input Setup-and-Hold Time Relative to Global Clock Input Signal for LVCMOS25 Standard.(1)						
T _{PSFD} /T _{PHFD}	Full Delay Global Clock and IFF without DCM(2)	XQ4VLX25	–	–	2.72/0.50	ns
		XQ4VLX40	–	3.06/0.44	3.11/0.44	ns
		XQ4VLX60	–	3.50/0.34	3.53/0.37	ns
		XQ4VLX80	2.96/0.26	–	–	ns
		XQ4VLX100	5.83/–0.09	6.76/–0.01	–	ns
		XQ4VLX160	–	3.76/0.88	–	ns
		XQ4VSX55	–	2.97/0.98	3.02/0.98	ns
		XQ4VFX60	–	3.54/0.59	3.58/0.62	ns
		XQ4VFX100	2.21/1.31	–	–	ns

Notes:

1. Setup time is measured relative to the global clock input signal with the fastest route and the lightest load. Hold time is measured relative to the global clock input signal with the slowest route and heaviest load.
2. IFF = input flip-flop or latch.
3. A zero “0” hold time listing indicates no hold time or a negative hold time. Negative values can not be guaranteed best-case, but if a “0” is listed, there is no positive hold time.

ChipSync Source-Synchronous Switching Characteristics

The parameters in this section provide the necessary values for calculating timing budgets for Virtex-4Q source-synchronous transmitter and receiver data-valid windows.

Table 55: Duty Cycle Distortion and Clock-Tree Skew

Symbol	Description	Device	Speed Grade		Units
			-11	-10	
T_{DCD_CLK}	Global Clock Tree Duty Cycle Distortion ⁽¹⁾	All	150	150	ps
T_{CKSKEW}	Global Clock Tree Skew ⁽²⁾	XQ4VLX25	–	110	ps
		XQ4VLX40	–	180	ps
		XQ4VLX60	–	180	ps
		XQ4VLX80	230	–	ps
		XQ4VLX100	310	350	ps
		XQ4VLX160	–	350	ps
		XQ4VSX55	–	190	ps
		XQ4VFX60	–	190	ps
		XQ4VFX100	230	–	ps
T_{DCD_BUFIO}	I/O clock tree duty cycle distortion	All	100	100	ps
	I/O clock tree skew across one clock region	All	50	50	ps
$T_{BUFIOSKEW}$	I/O clock tree skew across multiple clock regions	All	50	50	ps
T_{DCD_BUFR}	Regional clock tree duty cycle distortion	All	250	250	ps
$T_{BUFIO_MAX_FREQ}$ ⁽³⁾	I/O clock tree MAX frequency	All	710	645	MHz
$T_{BUFR_MAX_FREQ}$	Regional clock tree MAX frequency	All	250	250	MHz

Notes:

1. These parameters represent the worst-case duty cycle distortion observable at the pins of the device using LVDS output buffers. For cases where other I/O standards are used, IBIS can be used to calculate any additional duty cycle distortion that might be caused by asymmetrical rise/fall times.
2. The T_{CKSKEW} value represents the worst-case clock-tree skew observable between sequential I/O elements. Significantly less clock-tree skew exists for I/O registers that are close to each other and fed by the same or adjacent clock-tree branches. Use the Xilinx FPGA_Editor and Timing Analyzer tools to evaluate clock skew specific to the application.
3. Maximum frequency for operation outside of the industrial temperature range is 500 MHz.

Table 56: Package Skew

Symbol	Description	Device	Package	Value	Units
T _{PKGSKEW}	Package Skew ⁽¹⁾	XQ4VLX25	SF363	90	ps
			FF668	110	ps
		XQ4VLX40	FF668	110	ps
		XQ4VLX60	EF668	130	ps
			FF668	130	ps
			FF1148	140	ps
		XQ4VLX80	FF1148	155	ps
		XQ4VLX100	FF1148	140	ps
		XQ4VLX160	FF1148	145	ps
		XQ4VSX55	FF1148	145	ps
		XQ4VFX60	EF672	110	ps
		XQ4VFX100	FF1152	150	ps

Notes:

1. These values represent the worst-case skew between any two balls of the package: shortest flight time to longest flight time from pad to ball (7.1 ps/mm).
2. Package trace length information is available for these device/package combinations. This information can be used to deskew the package.

Table 57: Sample Window

Symbol	Description	Device	Speed Grade		Units
			-11	-10	
T _{SAMP}	Sampling Error at Receiver Pins ⁽¹⁾	All	500	550	ps
T _{SAMP_BUFIO}	Sampling Error at Receiver Pins using BUFIO ⁽²⁾	All	400	450	ps

Notes:

1. This parameter indicates the total sampling error of Virtex-4 FPGA DDR input registers across voltage, temperature, and process. The characterization methodology uses the DCM to capture the DDR input registers' edges of operation. These measurements include:
 - CLK0 DCM jitter
 - DCM accuracy (phase offset)
 - DCM phase shift resolution
 These measurements do not include package or clock tree skew.
2. This parameter indicates the total sampling error of Virtex-4 FPGA DDR input registers across voltage, temperature, and process. The characterization methodology uses the BUFIO clock network and IDELAY to capture the DDR input registers' edges of operation. These measurements do not include package or clock tree skew.

Table 58: ChipSync™ Pin-to-Pin Setup/Hold and Clock-to-Out

Symbol	Description	Speed Grade		Units
		-11	-10	
Data Input Setup-and-Hold Times Relative to a Forwarded Clock Input Pin Using BUFIO				
T _{PSCS} /T _{PHCS}	Setup/hold of I/O clock across multiple clock regions	-0.45/1.08	-0.44/1.17	ns
Pin-to-Pin Clock-to-Out Using BUFIO				
T _{ICKOFCS}	Clock-to-Out of I/O clock across multiple clock regions	4.54	5.02	ns

Production Stepping

The Virtex-4Q FPGA stepping identification system denotes the capability improvement of production released devices. By definition, devices from one stepping are functional supersets of previous devices. Bitstreams compiled for a device with an earlier stepping are guaranteed to operate correctly in subsequent device steppings.

New device steppings can be shipped in place of earlier device steppings. Existing production designs are guaranteed on new device steppings. To take advantage of the capabilities of a newer device stepping, customers are able to order a new stepping version and compile a new bitstream.

Production devices are marked with a stepping version, with the exception of some step 1 devices. Designs should be compiled with a CONFIG STEPPING parameter set to a specific stepping version.

This parameter is set in the UCF file:

```
CONFIG STEPPING = "#";
```

Where

= the stepping version

Table 59 shows the JTAG ID code by step.

Table 59: JTAG ID Code by Step

Device	ID Code	Stepping
XQ4VLX25	A	2
XQ4VLX40	5	2
XQ4VLX60	4 or 5	2
XQ4VLX80	5	2
XQ4VLX100	4 or 5	2
XQ4VLX160	4 or 5	2
XQ4VSX55	4	2
XQ4VFX60	8	1
XQ4VFX100	6	1

Current Virtex-4Q Production Devices

Table 60 summarizes the current production LX and SX device stepping.

Table 60: Current LX and SX Production Devices

LX/SX Device Stepping	Step 2
Example Ordering Code	XQ4VLX60-10FF668M
Device steppings shipped when ordered per Example Ordering Code	Step 2 only (see Table 59)
Capability Improvements	<ul style="list-style-type: none"> • T_{CONFIG} requirement is removed • DCM_RESET requirement is removed • DCM_INPUT_CLOCK_STOP requirement is removed by a macro (automatically inserted by ISE software)
CONFIG STEPPING parameter (must be set in UCF file)	"2"
Minimum Software Required	ISE 7.1i SP4
Minimum Speed Specification Required	1.58

Table 61 summarizes the current production FX device stepping.

Table 61: Current FX Production Devices

FX Device Stepping	Step 1
Example Ordering Code	XQ4VFX60-10EF672M
Device steppings shipped when ordered per Example Ordering Code	Step 1 only (see Table 59)
Capability Improvements	See FX Errata for details
CONFIG STEPPING parameter (must be set in UCF file)	"1"
Minimum Software Required	ISE 8.1i SP2
Minimum Speed Specification Required	1.58

Revision History

The following table shows the revision history for this document.

Date	Version	Revisions
11/29/06	1.0	Initial Xilinx release.
10/11/07	1.1	<ul style="list-style-type: none"> • SPEED SPECIFICATION version for this data sheet release: v1.67. • Updated template. • Added support for industrial temperature range devices: XQ4VLX100-10FF1148I, and XQ4VLX160-10FF1148I. • Added section Master/Slave SelectMAP Parameters, page 27. • Other updates and fixes.
12/20/07	1.2	<ul style="list-style-type: none"> • Updated document template. • Updated URLs. • Added support for XQ4VFX60-10EF672M and XQ4FVFX60-10EF672I. • Other minor fixes.
02/11/08	1.3	Added support for XQ4VLX40-10FF668I.
05/05/08	1.4	<ul style="list-style-type: none"> • Added support for XQ4VLX40-10FF668M. • Added I-Grade and M-Grade columns and updated values to Table 4, page 3, Table 38, page 26, and Table 50, page 34 through Table 54, page 36. • Updated values in Table 5, page 4. • Updated device production status in Table 13, page 9. • Added section PowerPC Switching Characteristics, page 10. • Added Table 24, page 16. • Added section Ethernet MAC Switching Characteristics, page 18. • Added note to Table 41, page 30 regarding support for MR mode. • Updated values in Table 43, page 30. • Added parameters DCM_RESET(3) and DCM_INPUT_CLOCK_STOP to Table 46, page 32. • Added Table 61, page 40. • Updated trademark notations. • Removed Notice of Disclaimer.
10/16/09	1.5	<ul style="list-style-type: none"> • Added EF668 package to XQ4VLX60 in Table 56, page 38. • Added Notice of Disclaimer, page 41.
04/27/10	1.6	Changed the document classification from Preliminary Product Specification to Product Specification. Replaced "QPro Virtex-4 FPGA" with "Virtex-4Q FPGA" throughout. Removed XQ4VLX25 I-grade from Table 4 , Table 50 , Table 51 , Table 52 , Table 53 , and Table 54 . (This device was planned but never opened for order entry.)
12/21/11	2.0	Revised the first page summary to incorporate adding the XQ4VLX80 and XQ4VFX100 in -11 speed specification for industrial temperature ranges only throughout this data sheet. Also added the XQ4VLX100 -11 speed specification industrial temperature range throughout this data sheet.

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